```
=> fil reg
FILE 'REGISTRY' ENTERED AT 11:29:13 ON 30 JAN 2008
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STRUCTURE FILE UPDATES:   29 JAN 2008  HIGHEST RN 1001040-86-3
DICTIONARY FILE UPDATES:  29 JAN 2008  HIGHEST RN 1001040-86-3

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TSCA INFORMATION NOW CURRENT THROUGH June 29, 2007

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experimental property data in the original document.  For information
on property searching in REGISTRY, refer to:

http://www.cas.org/support/stngen/stndoc/properties.html

=> d sta que l55
L30                 STR
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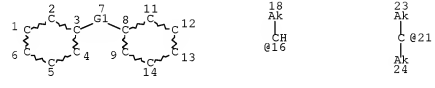


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VAR G1=CH2/16/21
NODE ATTRIBUTES:
CONNECT IS E1  RC AT  18
CONNECT IS E1  RC AT  23
CONNECT IS E1  RC AT  24
DEFAULT MLEVEL IS ATOM
DEFAULT ECLEVEL IS LIMITED

GRAPH ATTRIBUTES:
RSPEC   4   8
NUMBER OF NODES IS  18

STEREO ATTRIBUTES: NONE
L31                 SCR 2043
L33                 SCR 1992
L35                 SCR 2039 OR 2054 OR 2016 OR 2021 OR 2026 OR 1932
L37         65047 SEA FILE=REGISTRY SSS FUL L30 AND L31 AND L33 NOT L35
L38         23861 SEA FILE=REGISTRY ABB=ON  PLU=ON  L37 AND POLYURETHAN?/PCT
L39          1066 SEA FILE=REGISTRY ABB=ON  PLU=ON  L37 AND POLYISOCYAN?/PCT
L40                 STR
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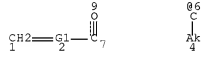
NODE ATTRIBUTES:
NSPEC IS RC AT 2
NSPEC IS RC AT 3
CONNECT IS M1 RC AT 3
DEFAULT MLEVEL IS ATOM
DEFAULT ECLEVEL IS LIMITED

GRAPH ATTRIBUTES:
RING(S) ARE ISOLATED OR EMBEDDED
NUMBER OF NODES IS 3

STEREO ATTRIBUTES: NONE
L42 42875 SEA FILE=REGISTRY SUB=L37 SSS FUL L40
L43 43239 SEA FILE=REGISTRY ABB=ON PLU=ON (L38 OR L39 OR L42)
L44 STR



VAR G1=CH/6
NODE ATTRIBUTES:
CONNECT IS E1 RC AT 4
DEFAULT MLEVEL IS ATOM
DEFAULT ECLEVEL IS LIMITED

GRAPH ATTRIBUTES:
RING(S) ARE ISOLATED OR EMBEDDED
NUMBER OF NODES IS 6

STEREO ATTRIBUTES: NONE
L46 6906 SEA FILE=REGISTRY SUB=L43 SSS FUL L44
L47 7057 SEA FILE=REGISTRY ABB=ON PLU=ON L43 AND POLYACRYL?/PCT
L48 7304 SEA FILE=REGISTRY ABB=ON PLU=ON (L46 OR L47)
L49 6318 SEA FILE=REGISTRY ABB=ON PLU=ON L43 AND POLYVINYL?/PCT
L50 11962 SEA FILE=REGISTRY ABB=ON PLU=ON (L48 OR L49)
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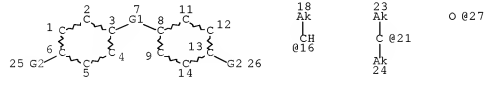
L52 STR



VAR G1=CH2/16/21
VAR G2=27/X
NODE ATTRIBUTES:
CONNECT IS M1 RC AT 27
DEFAULT MLEVEL IS ATOM
DEFAULT ECLEVEL IS LIMITED

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GRAPH ATTRIBUTES:
RSPEC   4   8
NUMBER OF NODES IS  21

STEREO ATTRIBUTES: NONE
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L55         7931 SEA FILE=REGISTRY ABB=ON  PLU=ON  (L51 OR L54)


=> fil hcaplus
FILE 'HCAPLUS' ENTERED AT 11:29:35 ON 30 JAN 2008
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FILE LAST UPDATED: 29 Jan 2008  (20080129/ED)

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 This file contains CAS Registry Numbers for easy and accurate
 substance identification.

=> d l109 bib abs hitstr retable tot

L109 ANSWER 1 OF 3  HCAPLUS  COPYRIGHT 2008 ACS on STN
AN   2003:777867  HCAPLUS  Full-text
DN   139:278082
TI   Curable liquid resin composition
IN   Sugimoto, Masanobu; Sugimoto, Hideki; Shigemoto,
     Takeo; Komiya, Zen; Ukachi, Takashi
PA   DSM N.V., Neth.; JSR Corporation
SO   PCT Int. Appl., 25 pp.
     CODEN: PIXXD2
DT   Patent
LA   English
FAN.CNT 1
     PATENT NO.          KIND   DATE        APPLICATION NO.        DATE
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             CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH,
             GM, HR, HU, ID, IL, IN, IS, KE, KG, KP, KR, KZ, LC, LK, LR, LS,
             LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PH,
             PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ,
             UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW
         RW: GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY,
             KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES,
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FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR,
BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG

JP 2003277453 A 20031002 JP 2002-88363 20020327 <--
AU 2003225418 A1 20031008 AU 2003-225418 20030327 <--
EP 1487889 A1 20041222 EP 2003-745037 20030327 <--
EP 1487889 B1 20080123
R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT,
IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK
CN 1643010 A 20050720 CN 2003-807013 20030327 <--
US 20052/2829 A1 20051208 US 2005-507016 20050718 <--
PRAI JP 2002-88363 A 2020327 <--
WO 2003-NL231 W 2003032/ <--

AB A curable liquid resin composition comprising: (a) 5-94 parts urethane (meth)acrylate comprising a polyether backbone, ≥1 urethane group and ≥1 (meth)acrylate end group, (b) 5-94 parts polymerizable monomer, and (c) 0.01-10 parts photoinitiator, where the cured product of the composition has a glass transition temperature, Tg, 30-85° and a stress relaxation time ≤30 min. Typically the cured coated optical fiber has Young's modulus 750 MPa, coating Tg 73°, and stress relaxation time 2 min.

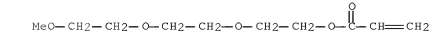
IT 605686-29-1P, Ethoxylated bisphenol A-2-hydroxyethyl acrylate-isobornyl acrylate-propoxylated bisphenol A-2,4-tolylene diisocyanate-vinylcaprolactam-Viscoat 320 copolymer 605686-30-4P, 2-Hydroxyethyl acrylate-isobornyl acrylate-propoxylated bisphenol A-2,4-tolylene diisocyanate-vinylcaprolactam-Viscoat 320 copolymer 605686-31-5P 606130-26-1P, Ethoxylated propoxylated bisphenol A-2-hydroxyethyl acrylate-isobornyl acrylate-polypropylene oxide-2,4-tolylene diisocyanate-vinylcaprolactam-Viscoat 320 copolymer 606130-27-2P, Butylene oxide-ethoxylated propoxylated bisphenol A-ethylene oxide-2-hydroxyethyl acrylate-isobornyl acrylate-2,4-tolylene diisocyanate-vinylcaprolactam-Viscoat 320 copolymer
RL: IMF (Industrial manufacture); POF (Polymer in formulation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(curable liquid polyurethane acrylate resin compns. for optical fibers)

RN 605686-29-1 HCAPLUS

CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 2,4-diisocyanato-1-methylbenzene, 1-ethenylhexahydro-2H-azepin-2-one, 2-[2-(2-methoxymethylethoxy)methylethoxy]methylethyl 2-propenoate, α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly(oxy-1,2-ethanediyl)], α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] and rel-(1R,2R,4R)-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl 2-propenoate (9CI) (CA INDEX NAME)

CM 1

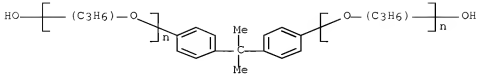
CRN 54398-08-2
CMF C13 H24 O5
CCI IDS



3 (D1—Me)

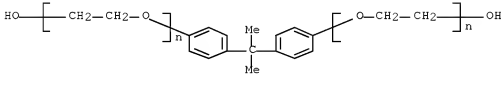
CM 2

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



CM 3

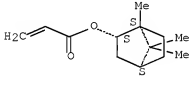
CRN 32492-61-8
CMF (C2 H4 O)n (C2 H4 O)n C15 H16 O2
CCI PMS



CM 4

CRN 5888-33-5
CMF C13 H20 O2

Relative stereochemistry.

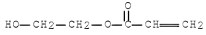


CM 5

CRN 2235-00-9
CMF C8 H13 N O

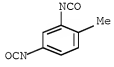
CM 6

CRN 818-61-1
CMF C5 H8 O3



CM 7

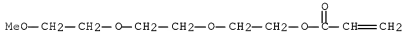
CRN 584-84-9
CMF C9 H6 N2 O2



RN 605686-30-4 HCAPLUS
CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 2,4-diisocyanato-1-methylbenzene, 1-ethenylhexahydro-2H-azepin-2-one, 2-[2-(2-methoxymethylethoxy)methylethoxy]methylethyl 2-propenoate, α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] and rel-(1R,2R,4R)-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl 2-propenoate (9CI) (CA INDEX NAME)

CM 1

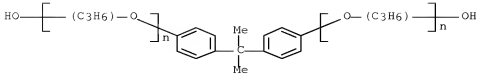
CRN 54398-08-2
CMF C13 H24 O5
CCI IDS



3 (D1—Me)

CM 2

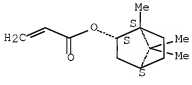
CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



CM 3

CRN 5888-33-5
CMF C13 H20 O2

Relative stereochemistry.

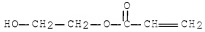


CM 4

CRN 2235-00-9
CMF C8 H13 N O

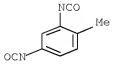
CM 5

CRN 818-61-1
CMF C5 H8 O3



CM 6

CRN 584-84-9
CMF C9 H6 N2 O2



RN 605686-31-5 HCAPLUS
CN 2-Propenoic acid, (octahydro-4,7-methano-1H-indene-5,?-diyl)bis(methylene) ester, polymer with 1-ethenyl-2-pyrrolidinone, ethyloxirane, 2-hydroxyethyl 2-propenoate, 5-isocyanato-1-(isocyanatomethyl)-1,3,3-trimethylcyclohexane, α,α'-[(1-methylethylidene)di-4,1-cyclohexanediyl]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]], α,α'-[(1-methylethylidene)di-4,1-cyclohexanediyl]bis[ω-[(1-oxo-2-propenyl)oxy]poly(oxy-1,2-ethanediyl)], oxirane and rel-(1R,2R,4R)-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl 2-propenoate (9CI) (CA INDEX NAME)

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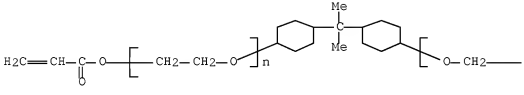
CRN 77866-18-3
CMF (C2 H4 O)n (C2 H4 O)n C21 H32 O4
CCI PMS

PAGE 1-A



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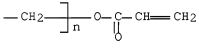

CM 2

CRN 70640-72-1
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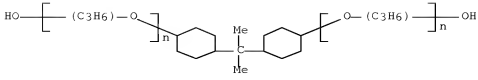
CCI IDS, PMS



CM 3

CRN 42594-17-2
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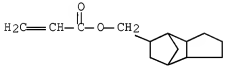
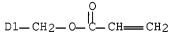
CCI IDS

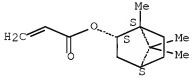




CM 4

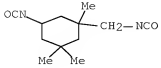
CRN 5888-33-5
CMF C13 H20 O2

Relative stereochemistry.



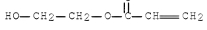
CM 5

CRN 4098-71-9
CMF C12 H18 N2 O2



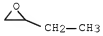
CM 6

CRN 818-61-1
CMF C5 H8 O3



CM 7

CRN 106-88-7
CMF C4 H8 O



CM 8

CRN 88-12-0
CMF C6 H9 N O

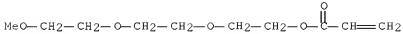
CM 9

CRN 75-21-8
CMF C2 H4 O

RN 606130-26-1 HCAPLUS
CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 2,4-diisocyanato-1-methylbenzene, 1-ethenylhexahydro-2H-azepin-2-one, 2-[2-(2-methoxymethylethoxy)methylethoxy]methylethyl 2-propenoate, methyloxirane polymer with oxirane ether with 4,4'-(1-methylethylidene)bis[phenol] (2:1), and rel-(1R,2R,4R)-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl 2-propenoate (9CI) (CA INDEX NAME)

CM 1

CRN 54398-08-2
CMF C13 H24 O5
CCI IDS

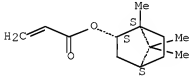


3 (D1—Me)

CM 2

CRN 5888-33-5
CMF C13 H20 O2

Relative stereochemistry.

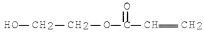


CM 3

CRN 2235-00-9
CMF C8 H13 N O

CM 4

CRN 818-61-1
CMF C5 H8 O3



CM 5

CRN 584-84-9
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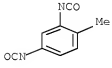

CM 6

CRN 65324-64-3
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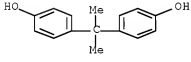
CM 7

CRN 80-05-7
CMF C15 H16 O2



CM 8

CRN 9003-11-6
CMF (C3 H6 O . C2 H4 O)x
CCI PMS

CM 9

CRN 75-56-9
CMF C3 H6 O

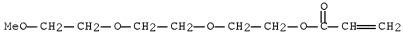
CM 10

CRN 75-21-8
CMF C2 H4 O

RN 606130-27-2 HCAPLUS
CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 2,4-diisocyanato-1-methylbenzene, 1-ethenylhexahydro-2H-azepin-2-one, ethyloxirane, 2-[2-(2-methoxymethylethoxy)methylethoxy]methylethyl 2-propenoate, methyloxirane polymer with oxirane ether with 4,4'-(1-methylethylidene)bis[phenol] (2:1), oxirane and rel-(1R,2R,4R)-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl 2-propenoate (9CI) (CA INDEX NAME)

CM 1

CRN 54398-08-2
CMF C13 H24 O5
CCI IDS

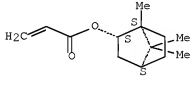


3 (D1—Me)

CM 2

CRN 5888-33-5
CMF C13 H20 O2

Relative stereochemistry.

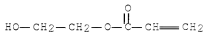


CM 3

CRN 2235-00-9
CMF C8 H13 N O

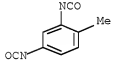
CM 4

CRN 818-61-1
CMF C5 H8 O3



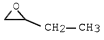
CM 5

CRN 584-84-9
CMF C9 H6 N2 O2



CM 6

CRN 106-88-7
CMF C4 H8 O



CM 7

CRN 75-21-8
CMF C2 H4 O

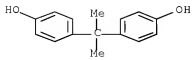
CM 8

CRN 65324-64-3
CMF C15 H16 O2 . 2 (C3 H6 O . C2 H4 O)x

CM 9

CRN 80-05-7

CMF C15 H16 O2



CM 10

CRN 9003-11-6
CMF (C3 H6 O . C2 H4 O)x
CCI PMS

CM 11

CRN 75-56-9
CMF C3 H6 O

CM 12

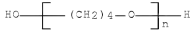
CRN 75-21-8
CMF C2 H4 O

IT 221291-73-2P, 2-Hydroxyethyl acrylate-IBXA-lauryl acrylate-poly(tetramethylene glycol)-2,4-tolylene diisocyanate-vinylcaprolactam copolymer
RL: IMF (Industrial manufacture); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(primary coating; curable liquid polyurethane acrylate resin compns. for optical fibers)
RN 221291-73-2 HCAPLUS
CN 2-Propenoic acid, dodecyl ester, polymer with 2,4-diisocyanato-1-methylbenzene, 1-ethenylhexahydro-2H-azepin-2-one, α-hydro-ω-hydroxypoly(oxy-1,4-butanediyl), 2-hydroxyethyl 2-propenoate and rel-(1R,2R,4R)-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl 2-propenoate (9CI) (CA INDEX NAME)

CM 1

CRN 25190-06-1
CMF (C4 H8 O)n H2 O

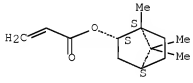
CCI PMS



CM 2

CRN 5888-33-5
CMF C13 H20 O2

Relative stereochemistry.

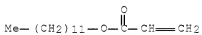


CM 3

CRN 2235-00-9
CMF C8 H13 N O

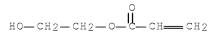
CM 4

CRN 2156-97-0
CMF C15 H28 O2



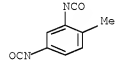
CM 5

CRN 818-61-1
CMF C5 H8 O3



CM 6

CRN 584-84-9
CMF C9 H6 N2 O2



RETABLE

Referenced Author (RAU)	Year (RPY)	VOL (RVL)	PG (RPG)	Referenced Work (RWK)	Referenced File
Asahi Chemical Ind	1995			EP 0656378 A	HCAPLUS
Jsr Corp	2000			WO 0011097 A	HCAPLUS
Jsr Corp	2001			WO 0147824 A	

L109 ANSWER 2 OF 3 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1999:156778 HCAPLUS Full-text
DN 130:238892
TI Liquid curable resin compositions for coating of optical fibers with excellent applicability at high speed
IN Sugimoto, Masanobu; Uchida, Hiroshi; Abe, Hiroshi; Ukaji, Takashi
PA JSR Co., Ltd., Japan; DSM N. V.
SO Jpn. Kokai Tokkyo Koho, 12 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 11060991	A	19990305	JP 1997-241933	19970822 <--
WO 9910443	A1	19990304	WO 1998-NL474	19980821 <--
W: CN, KR, US				
RW: AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE				
EP 1005514	A1	20000607	EP 1998-940678	19980821 <--
EP 1005514	B1	20031029		
R: BE, DE, FR, GB, IT				
PRAI JP 1997-241933	A	19970822 <--		
WO 1998-NL474	W	19980821 <--		

AB The compns. comprise (A) polymerizable compds. having (meth)acrylate groups, (B) reactive diluents with Mn <1000, and (C) polymerization initiators and show viscosity 500-3000 cP at 40° and activation energy for fluidization of 1-60 kJ/mol. Thus, a solution containing 8.7 g 2,4-TDI, 21.3 g isobornyl acrylate (I), 2,6-di-tert-butyl-p-cresol, dibutyltin dilaurate, and phenothiazine was treated with 3.8 g 2-hydroxyethyl acrylate, further treated with 65.6 g polytetramethylene glycol (Mn 2000) until free NCO of ≤0.1%,

stirred with I 14.2, N-vinylcaprolactam 6.3, and lauryl acrylate 7.3 g, mixed with 0.1 g Et2NH, and further mixed with 2.0 g bis(2,6-dimethoxybenzoyl)-2,4,4-trimethylpentylphosphine oxide to give a composition showing viscosity 1100 cP at 40°, the activation energy 50.3 kJ/mol, Young's modulus 61 kg/mm2, and good applicability on a precoated optical fiber core at high speed.

IT 221291-73-2P

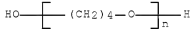
RL: DEV (Device component use); IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(acrylate polymer compns. for coating of optical fibers with good applicability at high speed)

RN 221291-73-2 HCAPLUS

CN 2-Propenoic acid, dodecyl ester, polymer with 2,4-diisocyanato-1-methylbenzene, 1-ethenylhexahydro-2H-azepin-2-one, α-hydro-ω-hydroxypoly(oxy-1,4-butanediyl), 2-hydroxyethyl 2-propenoate and rel-(1R,2R,4R)-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl 2-propenoate (9CI) (CA INDEX NAME)

CM 1

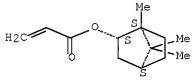
CRN 25190-06-1
CMF (C4 H8 O)n H2 O
CCI PMS



CM 2

CRN 5888-33-5
CMF C13 H20 O2

Relative stereochemistry.

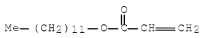


CM 3

CRN 2235-00-9
CMF C8 H13 N O

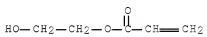
CM 4

CRN 2156-97-0
CMF C15 H28 O2



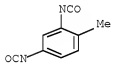
CM 5

CRN 818-61-1
CMF C5 H8 O3



CM 6

CRN 584-84-9
CMF C9 H6 N2 O2



L109 ANSWER 3 OF 3 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1999:8218 HCAPLUS Full-text
DN 130:55915
TI Optical glass fiber ribbon assemblies, and matrix-forming compositions and ink compositions for use in forming the ribbon assemblies
IN Zahora, Edward Paul; Murphy, Edward Joseph; Szum, David Michael; Vandeberg, John Thomas; Noren, Gerry Karl; Montgomery, Eva Irene
PA DSM N.V., Neth.
SO PCT Int. Appl., 58 pp.
CODEN: PIXXD2
DT Patent
LA English
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI WO 9857209	A1	19981217	WO 1998-NL340	19980611 <--
W: AU, BR, CA, CN, ID, JP, KR				
RW: AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE				

AU 9881319 A 19981230 AU 1998-81319 19980611 <--
EP 988571 A1 20000329 EP 1998-931119 19980611 <--
R: BE, DE, DK, FR, GB, IT, NL
JP 2002503199 T 20020129 JP 1999-502155 19980611 <--
PRAI US 1997-49064P P 19970611 <--
WO 1998-NL340 W 19980611 <--

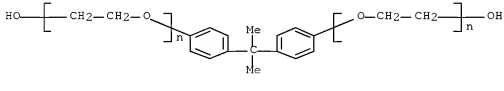
AB The ribbon assemblies, having the functional capability of providing mid-span access to individually coated optical fibers and comprising multiple optical glass fibers and a matrix material binding the optical fibers together, comprise optical fibers provided with ≥1 coatings, which, in turn, are coated with a radiation-curable ink comprising an adhesion-adjusting oligomer containing ≥1 radiation-curable functional groups bonded to a low-surface energy backbone and being substantially free of F and silicones and present in an amount sufficient to decrease the surface energy of the coating to a level providing less adhesion between the ink coating and the matrix material than between the ink coating and coating on the optical fibers. A radiation-curable ink composition contained as carrier poly(12-hydroxystearic acid) urethane acrylate 22.72, epoxy acrylate 20.84, hexafunctional aromatic urethane acrylate 9.17, aliphatic urethane triacrylate diluted 15% with hexanediol diacrylate 10.56, pentaerythritol tetraacrylate 11.59, hexanediol diacrylate 18.29, Troysol 98C (surfactant) 0.57, 2,6-di-tert-butyl-methyl-phenol 0.57, 2-benzyl-2-dimethylamino-1-(4-morpholinophenyl)-1-butane-1-one 1.14, and 2-methyl-1-(4-(methylthio)phenyl)2-(4,morpholinyl)-1-propanone 4.55 weight%.

IT 217202-60-3
RL: TEM (Technical or engineered material use); USES (Uses)
(oligomer, radiation curable coatings and ink compns. containing; for use in formation and mid-span access of optical glass fiber ribbon assemblies)

RN 217202-60-3 HCAPLUS
CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 1,3-diisocyanatomethylbenzene, α-hydro-ω-hydroxypoly(oxy-1,2-ethanediyl) and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly(oxy-1,2-ethanediyl)] (9CI) (CA INDEX NAME)

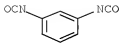
CM 1

CRN 32492-61-8
CMF (C2 H4 O)n (C2 H4 O)n C15 H16 O2
CCI PMS



CM 2

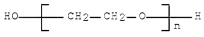
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1— Me

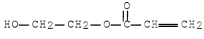
CM 3

CRN 25322-68-3
CMF (C2 H4 O)n H2 O
CCI PMS



CM 4

CRN 818-61-1
CMF C5 H8 O3



RETABLE

Referenced Author (RAU)	Year (RPY)	VOL (RVL)	PG (RPG)	Referenced Work (RWK)	Referenced File
Borden Inc	1997			EP 0780712 A	HCAPLUS
Dsm Nv	1997			WO 9705515 A	
Dsm Nv	1997			WO 9716469 A	HCAPLUS
Kaori, N	1996			US 5524164 A	
Lightguide Materials In	1997			WO 9718493 A	
Parker, T	1994			US 5373578 A	HCAPLUS
Petisce, J	1996			US 5539849 A	

=> d l110 bib abs hitstr retable tot

L110 ANSWER 1 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 2004:652644 HCAPLUS Full-text
DN 141:175592
TI Radiation-curable compositions containing two different radiation-curable urethane oligomers as coating for optical fiber
IN Hu, Shengkui; Weissberg, Alan B.
PA Ppg Industries Ohio, Inc., USA
SO U.S. Pat. Appl. Publ., 10 pp., Cont.-in-part of U.S. Ser. No. 360,176.
CODEN: USXXCO
DT Patent
LA English

FAN.CNT 2

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 2004157950	A1	20040812	US 2004-755130	20040109 <--
	US 7064154	B2	20060620		
	US 2004157949	A1	20040812	US 2003-360176	20030206 <--
	US 6872760	B2	20050329		
	WO 2004072144	A1	20040826	WO 2004-US3315	20040205 <--

W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI

RW: BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG

PRAI US 2003-360176 A2 20030206 <--
US 2004-755130 A 20040109

AB The compns., useful as coatings for and optical fibers and optical fiber arrays, comprise combinations of two different radiation-curable urethane oligomers, and ≥1 reactive monomers, wherein one of the oligomers has ≥3 functional groups that can undergo radiation cure and optionally comprises a lactone-modified polyol. Thus, N-vinyl-2-pyrrolidone 673.6, phenoxyethyl acrylate 164.2, isobornyl acrylate 126.6, dipentaerythritol pentaacrylate 286.4, a high -Tg polyurethane oligomer prepared from CN 120 (epoxy diacrylate), phenoxyethyl acrylate, IPDI and 2-hydroxyethyl acrylate 1005.7 and a high-elongation polyurethane oligomer prepared from m-tetramethylxylyl diisocyanate, isobornyl acrylate, trimethylolpropane, hydroxyethyl acrylate and polyTHF 2000 768.2 parts were mixed, applied to a glass plate and UV-cured at 1 J/cm2 under a D-lamp to give a film showing tensile strength 46 MPa and elongation 43%.

IT 733054-32-5P

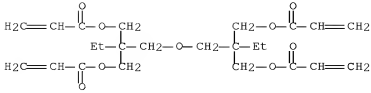
RL: IMF (Industrial manufacture); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(radiation-curable compns. containing two different radiation-curable urethane oligomers as coating for optical fiber)

RN 733054-32-5 HCAPLUS

CN 2-Propenoic acid, 2-[[2,2-bis[[(1-oxo-2-propenyl)oxy]methyl]butoxy]methyl]-2-ethyl-1,3-propanediyl ester, polymer with 1,3-bis(1-isocyanato-1-methylethyl)benzene, (chloromethyl)oxirane polymer with 4,4'-(1-methylethylidene)bis[phenol] di-2-propenoate, 2-ethyl-2-(hydroxymethyl)-1,3-propanediol, α-hydro-ω-hydroxypoly(oxy-1,4-butanediyl), 2-hydroxyethyl 2-propenoate, 5-isocyanato-1-(isocyanatomethyl)-1,3,3-trimethylcyclohexane, 2-[2-(2-methoxymethylethoxy)methylethoxy]methylethyl 2-propenoate, 2-phenoxyethyl 2-propenoate and rel-(1R,2R,4R)-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl 2-propenoate (9CI) (CA INDEX NAME)

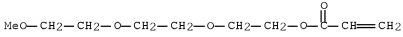
CM 1

CRN 94108-97-1
CMF C24 H34 O9



CM 2

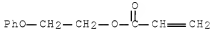
CRN 54398-08-2
CMF C13 H24 O5
CCI IDS



3 (D1—Me)

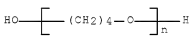
CM 3

CRN 48145-04-6
CMF C11 H12 O3



CM 4

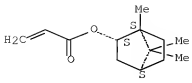
CRN 25190-06-1
CMF (C4 H8 O)n H2 O
CCI PMS



CM 5

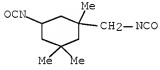
CRN 5888-33-5
CMF C13 H20 O2

Relative stereochemistry.



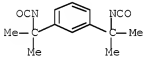
CM 6

CRN 4098-71-9
CMF C12 H18 N2 O2



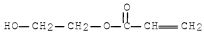
CM 7

CRN 2778-42-9
CMF C14 H16 N2 O2



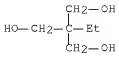
CM 8

CRN 818-61-1
CMF C5 H8 O3



CM 9

CRN 77-99-6
CMF C6 H14 O3

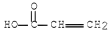


CM 10

CRN 53814-24-7
CMF (C15 H16 O2 . C3 H5 Cl O)x . 2 C3 H4 O2

CM 11

CRN 79-10-7
CMF C3 H4 O2



CM 12

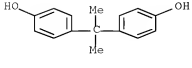
CRN 25068-38-6
CMF (C15 H16 O2 . C3 H5 Cl O)x
CCI PMS

CM 13

CRN 106-89-8
CMF C3 H5 Cl O

CM 14

CRN 80-05-7
CMF C15 H16 O2



RETABLE
Referenced Author |Year | VOL | PG | Referenced Work | Referenced

(RAU)	(RPY)	(RVL)	(RPG)	(RWK)	File
Anon	1986			EP 0168173	HCAPLUS
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Anon	1996			EP 0740210	HCAPLUS
Anon	1998			EP 0831372	HCAPLUS
Anon	1998			EP 0874012	HCAPLUS
Anon	2002			WO 02055447	HCAPLUS
Anon	2002			WO 02081526	HCAPLUS
Anon	2002			EP 0848836	HCAPLUS
Bishop	1988			US 4741958 A	HCAPLUS
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Chevreux	1991			US 5017433 A	HCAPLUS
Ishikawa	1999			US 5998497 A	HCAPLUS
Krongauz	2001			US 6265476 B1	HCAPLUS
Levandoski	2003			US 6596787 B1	HCAPLUS
Ohtaka	1998			US 5712035 A	HCAPLUS
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Szum	2000			US 6080483 A	HCAPLUS
Szum	2001			US 20010021727 A1	
Szum	2002			US 20020057885 A1	HCAPLUS
Szum	2002			US 20020102077 A1	
Szum	2002			US 6472450 B1	HCAPLUS
Takeyama	1990			US 4902440 A	HCAPLUS
Toler	2003			US 6596394 B1	HCAPLUS
Tortorello	2000			US 6023547 A	HCAPLUS
Tortorello	2000			US 6107361 A	HCAPLUS
Vazirani	1991			US RE33677 E	
Vorrier	1987			US H304 H	

L110 ANSWER 2 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 2004:467803 HCAPLUS Full-text
DN 141:24779
TI Soundproof, vibration-damping and lightweight laminated structural body
IN Nishiyama, Yuko; Arai, Yoshihide; Nemoto, Takashi; Inoue, Manabu; Horie, Kenichi
PA Three Bond Co., Ltd., Japan
SO PCT Int. Appl., 24 pp.
CODEN: PIXXD2
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	WO 2004048085	A1	20040610	WO 2003-JP14260	20031110 <--
	W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW				
	RW: BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG				
	AU 2003277643	A1	20040618	AU 2003-277643	20031110 <--

CN 1711171 A 20051221 CN 2003-80102702 20031110 <--
US 2006088706 A1 20060427 US 2005-533239 20050429 <--
PRAI JP 2002-341033 A 20021125 <--
WO 2003-JP14260 W 20031110

AB The laminated structural body with excellent processability, washability, and durability comprises a soundproof and vibration-damping substrate and a plurality of hard layers of fluid-like resin composition which are laminated directly on the substrate, wherein the hardnesses of at least two hard layers among the plurality of hard layers are different from each other and the hardest layer among the hard layers is desirably not formed, even partly, directly on the substrate but formed on the substrate through the other intermediate layer. The laminated structural body is used as covering for various information-relating devices or other devices. Thus, a hard-disk drive cover was coated with a photocurable acrylic resin composition containing a polyurethane acrylate (made by the reaction of MDI, Adeka BPX 11, and 2-hydroxyethyl acrylate), tetrahydrofurfuryl acrylate, and Irgacure 184 to a cured thickness of 0.2 mm; coated with a heat-curable composition containing Epikote 828, FXE 1000 (heat curing agent), and AS 40 (alumina powder) to a cured thickness of 0.2 mm; and cured by UV irradiation to obtain a cover with excellent soundproofing and vibration-damping effects.

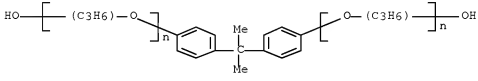
IT 698398-10-6P
RL: IMF (Industrial manufacture); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(soundproof, vibration-damping and lightwt. laminated structural body)

RN 698398-10-6 HCAPLUS

CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 1,1'-methylenebis[4-isocyanatobenzene], α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] and (tetrahydro-2-furanyl)methyl 2-propenoate (9CI) (CA INDEX NAME)

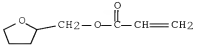
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



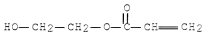
CM 2

CRN 2399-48-6
CMF C8 H12 O3



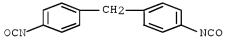
CM 3

CRN 818-61-1
CMF C5 H8 O3



CM 4

CRN 101-68-8
CMF C15 H10 N2 O2



RETABLE

Referenced Author (RAU)	Year (RPY)	VOL (RVL)	PG (RPG)	Referenced Work (RWK)	Referenced File
Kansai Paint Co Ltd	1978			JP 53-145851 A	HCAPLUS
Kansai Paint Co Ltd	1980			JP 55-17532 A	HCAPLUS
Kojima Press Industry C	2000			JP 200025536 A	
Nippon Steel Corp	1980			JP 55-41844 A	
Onkyo Corp	1984			JP 59-16969 Y	
Onkyo Corp	1984			JP 59-19930 Y	
Onkyo Corp	1984			JP 59-23203 Y	
Research Corp	1974			FR 2186616 A	HCAPLUS
Research Corp	1974			DE 2327718 A	HCAPLUS
Research Corp	1974			US 3833404 A	HCAPLUS
Research Corp	1974			JP 49-61267 A	HCAPLUS
Robert, B	1982			FR 2443290 A	HCAPLUS
Robert, B	1982			DE 2852828 A	HCAPLUS
Robert, B	1982			US 4346782 A	HCAPLUS
Robert, B	1982			JP 55-88876 A	HCAPLUS
Shimano Kogyo Kabushiki	1983			JP 58-18891 U	
Toyota Tsusho Kabushiki	1985			JP 60-73148 A	HCAPLUS

L110 ANSWER 3 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 2003:200563 HCAPLUS Full-text
DN 138:245595
TI Light-sensitive resin composition for dry-film photoresists
IN Takamiya, Hiroyuki; Hyuga, Atsuyoshi; Nakahara, Koichiro
PA Nichigo Morton Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 11 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE

PI JP 2003076016 A 20030314 JP 2001-272160 20010907 <--
PRAI JP 2001-272160 20010907 <--

AB The title composition contains a carboxyl-containing polymer which does not have an unsatd. group, a functionalized polymer, ethylenic unsatd. compds., and a photopolymn. initiator, wherein the functionalized polymer is prepared by reacting CH2=C(R1)-CO-O-R2-CO-NH-R3-NCO (R1 = H, methyl; R2 = -[(CO)xCHX1-(CHX2)yO]z-; x = 0, 1; y = 0-9 integer; z = 1-10 integer; X1-2 = H, methyl; R3 = diisocyanate residue) and a carboxyl group-containing polymer. The composition provides high resolution pattern, high flexibility, and good soldering characteristics.

IT 501423-82-1, Propoxylated bisphenol a-hexamethylene diisocyanate-polyethylene glycol copolymer methacrylate
RL: TEM (Technical or engineered material use); USES (Uses)
(light-sensitive resin composition for dry-film photoresists)

RN 501423-82-1 HCAPLUS

CN Poly[oxy(methyl-1,2-ethanediyl)], α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxy-, polymer with 1,6-diisocyanatohexane and α-hydro-ω-hydroxypoly(oxy-1,2-ethanediyl), 2-methyl-2-propenoate (ester) (9CI) (CA INDEX NAME)

CM 1

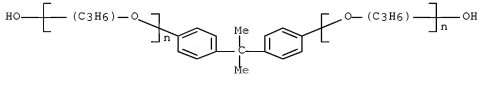
CRN 79-41-4
CMF C4 H6 O2

CM 2

CRN 501423-81-0
CMF (C8 H12 N2 O2 . (C3 H6 O)n (C3 H6 O)n C15 H16 O2 . (C2 H4 O)n H2 O)x
CCI PMS

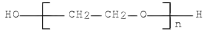
CM 3

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



CM 4

CRN 25322-68-3
CMF (C2 H4 O)n H2 O
CCI PMS



CM 5

CRN 822-06-0
CMF C8 H12 N2 O2

L110 ANSWER 4 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 2003:200562 HCAPLUS Full-text
DN 138:245594
TI Light-sensitive resin composition for dry-film photoresists
IN Takamiya, Hiroyuki; Hyuga, Atsuyoshi; Nakahara, Koichiro
PA Nichigo Morton Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 12 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2003076015	A	20030314	JP 2001-272159	20010907 <--
PRAI JP 2001-272159		20010907 <--		

AB The composition contains carboxy-containing polymers which does not contains an unsatd. group, 0.3-3.5 mmol/g unsatd. group-containing modified polymers, ethylenic unsatd. compds., and a photopolymn. initiator, wherein the modified polymer is the product of a carboxyl group-containing polymer and compound OCN-R3-NH-CO-R2-OCH2-C(-CH2-O-R2-CO-C(R1)=CH2)3 (R1 = H, methyl; R2 = -[(CO)xCHX1(CHX2)yO]z-; x = 0,1; 0-9 integer; z = 0-10 integer; X1-2 = H, methyl; R3 = organic group residue). The composition provides the dry-film photoresists of good characteristics on sensitivity, resolution, contact with a substrate, flexibility, developer-resistance, soldering, peeling and is suitable for printed circuit boards for semiconductor packaging and lead frame pattern.
IT 501423-82-1, Propoxylated bisphenol a-hexamethylene diisocyanate-polyethylene glycol copolymer methacrylate
RL: TEM (Technical or engineered material use); USES (Uses)
(ethylenic unsatd. compound; light-sensitive resin composition for dry-film photoresists)
RN 501423-82-1 HCAPLUS
CN Poly[oxy(methyl-1,2-ethanediyl)], α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxy-, polymer with 1,6-diisocyanatohexane and α-hydro-ω-hydroxypoly(oxy-1,2-ethanediyl), 2-methyl-2-propenoate (ester) (9CI) (CA INDEX NAME)

CM 1

CRN 79-41-4

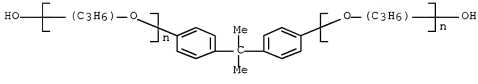
CMF C4 H6 O2

CM 2

CRN 501423-81-0
CMF (C8 H12 N2 O2 . (C3 H6 O)n (C3 H6 O)n C15 H16 O2 . (C2 H4 O)n H2 O)x
CCI PMS

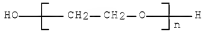
CM 3

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



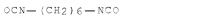
CM 4

CRN 25322-68-3
CMF (C2 H4 O)n H2 O
CCI PMS



CM 5

CRN 822-06-0
CMF C8 H12 N2 O2



L110 ANSWER 5 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 2003:200561 HCAPLUS Full-text
DN 138:245593
TI Light-sensitive resin composition for dry-film photoresists

IN Takamiya, Hiroyuki; Hyuga, Atsuyoshi; Nakahara, Koichiro
PA Nichigo Morton K. K., Japan
SO Jpn. Kokai Tokkyo Koho, 12 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2003076014	A	20030314	JP 2001-272158	20010907 <--
PRAI	JP 2001-272158		20010907	<--	

AB The composition contains carboxy-containing polymers which does not contain an unsatd. group, 0.3-3.5 mmol/g unsatd. group-containing polymers prepared by modifying a polymer with unsatd. compound having alicyclic epoxy groups, ethylenic unsatd. compds., and a photopolymn. initiator. The composition provides the dry-film photoresists of good characteristics on sensitivity, resolution, contact with a substrate, flexibility, developer-resistance, soldering, peeling and is suitable for printed circuit boards for semiconductor packaging and lead frame pattern.

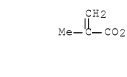
IT 501423-82-1, Propoxylated bisphenol a-hexamethylene diisocyanate-polyethylene glycol copolymer methacrylate
RL: TEM (Technical or engineered material use); USES (Uses)
(ethylenic unsatd. compound; light-sensitive resin composition for dry-film photoresists)

RN 501423-82-1 HCAPLUS

CN Poly[oxy(methyl-1,2-ethanediyl)], α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxy-, polymer with 1,6-diisocyanatohexane and α-hydro-ω-hydroxypoly(oxy-1,2-ethanediyl), 2-methyl-2-propenoate (ester) (9CI) (CA INDEX NAME)

CM 1

CRN 79-41-4
CMF C4 H6 O2

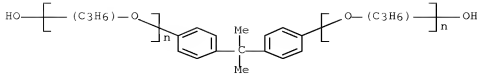


CM 2

CRN 501423-81-0
CMF (C8 H12 N2 O2 . (C3 H6 O)n (C3 H6 O)n C15 H16 O2 . (C2 H4 O)n H2 O)x
CCI PMS

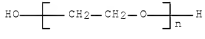
CM 3

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



CM 4

CRN 25322-68-3
CMF (C2 H4 O)n H2 O
CCI PMS



CM 5

CRN 822-06-0
CMF C8 H12 N2 O2

L110 ANSWER 6 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 2002:748356 HCAPLUS Full-text
DN 137:286435
TI Light-sensitive pattern-forming resin composition containing specific ethylenic unsaturated compounds for manufacturing electric circuit pattern
IN Hyuga, Atsuyoshi; Takamiya, Hiroyuki
PA Nichigo Morton K. K., Japan
SO Jpn. Kokai Tokkyo Koho, 9 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2002287347	A	20021003	JP 2001-87136	20010326 <--
PRAI	JP 2001-87136		20010326 <--		

AB The title composition contains a binder resin, ethylenic unsatd. compds., and a photopolymn. initiator, wherein the ethylenic unsatd. compds. contains an acrylic compound which has urethane bonds and has structure CH2=C(R)-C(=O)O-(R1O)m-C(=O)-NH-X-NH-C(=O)-(-O-CH2CH2CH2CH2CH2-C(=O))l-O- (R2O)n-Y-(OR2)n'-O-(C(=O)-CH2CH2CH2CH2CH2-O-)-C(=O)-NH-X-NH-C(=O)-(OR1)m'- O-C(=O)-C(R)=CH2 (R = H, C1-3 alkyl; R1-2 = C2-5 alkylene; X = 2-valent C2-20 hydrocarbon; Y = 2-valent bisphenol group without OH terminals; m,m',n,n' = 0-30 integer; l, l' = 1-10 integer). The composition provides good layer strength on various shapes of through holes and pattern of high resolution, the good contact with substrate, the good peeling off property.

IT 467227-39-8, Ethoxylated bisphenol A-ε-caprolactone-hexamethylene diisocyanate-propylene oxide block copolymer dimethacrylate
RL: TEM (Technical or engineered material use); USES (Uses)
(ethylenic unsatd. compds.; light-sensitive pattern-forming resin compns. for manufacturing elec. circuit pattern)

RN 467227-39-0 HCAPLUS

CN 2-Oxepanone, polymer with 1,6-diisocyanatohexane, α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly(oxy-1,2-ethanediyl)] and methyloxirane, bis(2-methyl-2-propenoate), block (9CI) (CA INDEX NAME)

CM 1

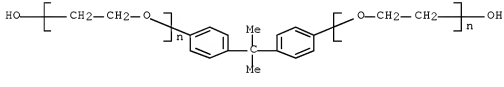
CRN 79-41-4
CMF C4 H6 O2

CM 2

CRN 467227-38-9
CMF (C8 H12 N2 O2 . C6 H10 O2 . C3 H6 O . (C2 H4 O)n (C2 H4 O)n C15 H16 O2)x
CCI PMS

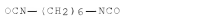
CM 3

CRN 32492-61-8
CMF (C2 H4 O)n (C2 H4 O)n C15 H16 O2
CCI PMS



CM 4

CRN 822-06-0
CMF C8 H12 N2 O2



CM 5

CRN 502-44-3
CMF C6 H10 O2

CM 6

CRN 75-56-9
CMF C3 H6 O

L110 ANSWER 7 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 2002:748355 HCAPLUS Full-text
DN 137:286434
TI Light-sensitive pattern-forming resin compositions containing specific ethylenic unsaturated compounds for manufacturing electric circuit pattern
IN Hyuga, Atsuyoshi; Takamiya, Hiroyuki
PA Nichigo Morton K. K., Japan
SO Jpn. Kokai Tokkyo Koho, 10 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2002287346	A	20021003	JP 2001-87135	20010326 <--
PRAI	JP 2001-87135		20010326 <--		

AB The title composition contains a binder resin, ethylenic unsatd. compds., and a photopolymn. initiator, wherein the ethylenic unsatd. compds. contains an acrylic compound which has urethane bonds and has structure CH2=C(R)-C(=O)O-(R1O)m-(C(=O)-CH2CH2CH2CH2CH2-O)l-C(=O)-NH-X-NH--C(=O)-O- (R2O)n-Y-(OR2)n'-O-C(=O)-NH-X-NH-C(=O)-(O-CH2CH2CH2CH2CH2-C(=O))l'-(OR1)m'- O-C(=O)-C(R)=CH2 (R = H, C1-3 alkyl; R1-2 = C2-5 alkylene; X = 2-valent C2-20 hydrocarbon; Y = 2-valent bisphenol group without OH terminals; m,m',n,n' = 0-30 integer; l, l' = 1-10 integer). The composition provides good layer strength on various shapes of through holes and pattern of high resolution, the good contact with substrate, the good peeling off property.

IT 467227-39-0
RL: TEM (Technical or engineered material use); USES (Uses)
(photopolymerizable unsatd. compound; light-sensitive pattern-forming resin compns. for manufacturing elec. circuit pattern)

RN 467227-39-0 HCAPLUS

CN 2-Oxepanone, polymer with 1,6-diisocyanatohexane, α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly(oxy-1,2-ethanediyl)] and methyloxirane, bis(2-methyl-2-propenoate), block (9CI) (CA INDEX NAME)

CM 1

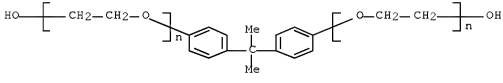
CRN 79-41-4
CMF C4 H6 O2

CM 2

CRN 467227-38-9
CMF (C8 H12 N2 O2 . C6 H10 O2 . C3 H6 O . (C2 H4 O)n (C2 H4 O)n C15 H16 O2)x
CCI PMS

CM 3

CRN 32492-61-8
CMF (C2 H4 O)n (C2 H4 O)n C15 H16 O2
CCI PMS



CM 4

CRN 822-06-0
CMF C8 H12 N2 O2

CM 5

CRN 502-44-3
CMF C6 H10 O2

CM 6

CRN 75-56-9
CMF C3 H6 O

L110 ANSWER 8 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 2002:256014 HCAPLUS Full-text
DN 136:284505
TI Wax-like polymerizable dental material and shaped product
IN Sun, Benjamin J.; Lichkus, Andrew M.
PA Dentsply International Inc., USA
SO PCT Int. Appl., 17 pp.
CODEN: PIXXD2
DT Patent
LA English
FAN.CNT 7

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	WO 2002026197	A2	20020404	WO 2001-US29970	20010925 <--
	WO 2002026197	A3	20030814		
	W: CA, JP				
	RW: AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR				
	US 2002061493	A1	20020523	US 2001-682440	20010904 <--
	US 6592369	B2	20030715		
	CA 2408440	A1	20020404	CA 2001-2408440	20010925 <--
	EP 1351649	A2	20031015	EP 2001-971342	20010925 <--
	EP 1351649	B1	20070822		
	R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, FI, CY, TR				
	JP 2004512064	T	20040422	JP 2002-530028	20010925 <--
	AT 370720	T	20070915	AT 2001-971342	20010925 <--
	US 2003190585	A1	20031009	US 2003-431712	20030508 <--
	US 7024770	B2	20060411		
PRAI	US 2000-670364	A	20000926	<--	
	US 2000-237523P	P	20001004	<--	
	US 2001-682440	A	20010904	<--	
	WO 2001-US29970	W	20010925	<--	

AB The invention provides high strength dental polymeric dental products made from wax-like polymerizable dental material. These dental products have superior strength compared to products formed from prior wax-like polymerizable materials. Prior wax-like polymerizable materials do not form strong enough polymeric material for making dentures. High strength dentures are made by positioning artificial teeth in wax-like polymerizable dental material of the invention. This material is then shaped and polymerized to the form a denture base of high strength dental polymeric material. These dentures are completed without forming wax and without applying inorg. plaster to the artificial teeth. An oligomer was obtained by the reaction of trimethyl-1,6-diisocyanatohexane with bisphenol A propoxylate in the presence of dibutyltin dilaurate. A viscous paste-like isocyanate end-capped intermediate product (oligomer)was formed and to this product was added 2-

hydroxyethyl methacrylate and BHT as the inhibitor. An oligomer was collected from the reactor as a semi-translucent flexible solid. A light curable polymerizable material was prepared by stirring a liquid of the above oligomer, 2,4,6-trimethylbenzoyldiphenylphosphine oxide, a solution containing camphorquinone, Et 4-dimethylaminobenzoate and 1,6-hexanediol dimethacrylate, red acetate fibers and pigment.

IT 406499-81-8P

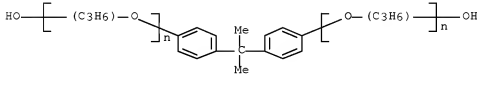
RL: SPN (Synthetic preparation); THU (Therapeutic use); BIOL (Biological study); PREP (Preparation); USES (Uses)
(wax-like polymerizable dental material and shaped product)

RN 406499-81-8 HCAPLUS

CN 2-Propenoic acid, 2-methyl-, 2-hydroxyethyl ester, polymer with 1,6-diisocyanatotrimethylhexane, α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] and octadecyl 2-propenoate (9CI) (CA INDEX NAME)

CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



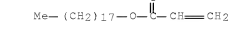
CM 2

CRN 28679-16-5
CMF C11 H18 N2 O2
CCI IDS

3 (D1—Me)

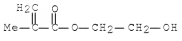
CM 3

CRN 4813-57-4
CMF C21 H40 O2



CM 4

CRN 868-77-9
CMF C6 H10 O3



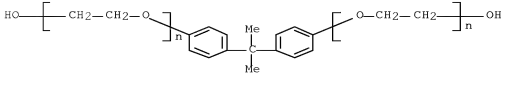
L110 ANSWER 9 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 2002:21706 HCAPLUS Full-text
DN 136:71306
TI Active energy radiation-curable coating compositions
IN Deguchi, Yoshinobu; Abe, Yoichi; Ishikawa, Hidenobu
PA Dainippon Ink and Chemicals, Inc., Japan
SO Jpn. Kokai Tokkyo Koho, 7 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 2002003748	A	20020109	JP 2000-191160	20000626 <--
PRAI JP 2000-191160		20000626 <--		

AB The title compns., with good strength and elasticity, comprise (a) polyurethane acrylates derived from (hydrogenated) bisphenol alkylene oxide adducts (e.g., polyoxyethylene bisphenol A adduct, polyoxyethylene bisphenol F adduct), organic diisocyanates (e.g., TDI, IPDI), and OH-containing radical polymerizable monomers (e.g., 2-hydroxyethyl acrylate, hydroxypropyl acrylate) and (b) radical polymerizable monomers containing ≥20% N-containing monomers [e.g., (meth)acryloyl morpholine, N-vinylpyrrolidone, N-vinyl caprolactam, N-vinyl acetamide, and/or N-vinyl formamide].
IT 385441-15-6
RL: POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); USES (Uses)
(active energy radiation-curable coating compns.)
RN 385441-15-6 HCAPLUS
CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 1-ethenyl-2-pyrrolidinone, 5-isocyanato-1-(isocyanatomethyl)-1,3,3-trimethylcyclohexane and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly(oxy-1,2-ethanediyl)] (9CI) (CA INDEX NAME)

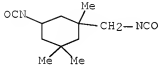
CM 1

CRN 32492-61-8
CMF (C2 H4 O)n (C2 H4 O)n C15 H16 O2
CCI PMS



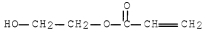
CM 2

CRN 4098-71-9
CMF C12 H18 N2 O2



CM 3

CRN 818-61-1
CMF C5 H8 O3



CM 4

CRN 88-12-0
CMF C6 H9 N O

L110 ANSWER 10 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 2001:805342 HCAPLUS Full-text
DN 135:358836
TI Water-absorbing polymers and fiber sheets containing the same with good gel strength and elongation
IN Otaguro, Takahiro; Kashiwada, Toshinobu; Suzuki, Noriko; Hosokawa, Minoru
PA Lion Corp., Japan
SO Jpn. Kokai Tokkyo Koho, 62 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2001310949	A	20011106	JP 2000-128466	20000427 <--

PRAI JP 2000-128466 20000427 <--

AB The polymers are manufactured by irradiating electromagnetic or particulate ionized radiation on ≥1 solns. chosen from (A) aqueous solns. of poly(vinyl alcs.) bearing anionic or cationic groups, (B) aqueous solns. of poly(vinyl alc.), water-soluble polymers having oxyethylene and/or oxypropylene units with mol. weight ≥100, etc. Thus, a rayon-polypropylene nonwoven fabric sheet was impregnated with PVA S 2217 [SO3H-containing poly(vinyl alc.)] and irradiated with electron beam at dose 40 kGy, resulting in good gel strength and elongation.

IT 372516-65-9P

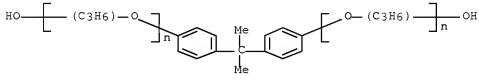
RL: IMF (Industrial manufacture); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PREP (Preparation); PROC (Process); USES (Uses)
(water-absorbing polymers and fiber sheets containing the same with good gel strength and elongation)

RN 372516-65-9 HCAPLUS

CN 2-Pyrrolidinone, 1-ethenyl-, polymer with α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



CM 2

CRN 88-12-0
CMF C6 H9 N O

L110 ANSWER 11 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN

AN 2000:272014 HCAPLUS Full-text

DN 132:266296

TI Alkali-resistant glass fiber-reinforced polyurethane acrylate composition and its product

IN Iwagi, Futaji; Miyawaki, Takeshi; Morita, Masaru

PA Nippon Shokubai Kagaku Kogyo Co., Ltd., Japan

SO Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF

DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2000119406	A	20000425	JP 1998-296660	19981019 <--
PRAI	JP 1998-296660		19981019 <--		

AB The title composition comprises polyurethane acrylates (e.g., derived from hydroxyethyl methacrylate, Bisol 2PN, and Sumidur 44V10) and SiO2-Al2O3-MO type glass fibers including ZnO, B2O3, and TiO2.

IT 61509-43-1

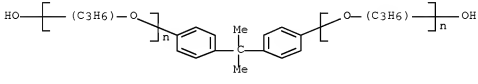
RL: POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); USES (Uses)
(alkali-resistant glass fiber-reinforced polyurethane acrylate composition and product)

RN 61509-43-1 HCAPLUS

CN 2-Propenoic acid, 2-methyl-, 2-hydroxyethyl ester, polymer with 1,1'-methylenebis[4-isocyanatobenzene] and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

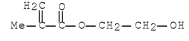
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



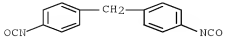
CM 2

CRN 868-77-9
CMF C6 H10 O3



CM 3

CRN 101-68-8
CMF C15 H10 N2 O2



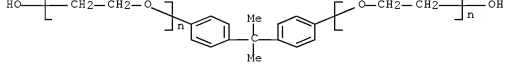
L110 ANSWER 12 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1999:802954 HCAPLUS Full-text
DN 132:37066
TI Transparent and wear-resistant coating and its production method
IN Kondo, Satoshi; Higuchi, Toshihiko; Shibuya, Takashi; Yamamoto, Hiroshi
PA Asahi Glass Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 15 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 11349853	A	19991221	JP 1998-163935	19980611 <--
PRAI JP 1998-163935		19980611 <--		

AB The coating, on the surface of a transparent synthetic polymer substrate, comprises ≥2 coating layers of (A) an active energy-curable compound having ≥2 functional groups and (B) a top layer of polysilazane and UV absorber mixture Thus, a primer coat was made from mainly a copolymer of dipentaerythritol acrylate and hexamethylenediisocyanate isocyanurate with solvents and additives and a topcoat was made from UL 110 solution (xylene containing 10% ZnO and 10% perhydropolysilazane).
IT 220736-33-4, Ethoxylated bisphenol A-hexamethylene diisocyanate-2-hydroxyethyl acrylate copolymer
RL: PRP (Properties); TEM (Technical or engineered material use); USES (Uses)
(primer; transparent and wear-resistant coating and its production method)
RN 220736-33-4 HCAPLUS
CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 1,6-diisocyanatohexane and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly(oxy-1,2-ethanediyl)] (9CI) (CA INDEX NAME)

CM 1

CRN 32492-61-8
CMF (C2 H4 O)n (C2 H4 O)n C15 H16 O2
CCI PMS

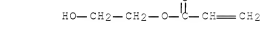


CM 2

CRN 822-06-0
CMF C8 H12 N2 O2

CM 3

CRN 818-61-1
CMF C5 H8 O3



L110 ANSWER 13 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1999:156339 HCAPLUS Full-text
DN 130:210574
TI Manufacture of transparent coated moldings having abrasion-resistant coating layer
IN Kondou, Satoshi; Higuchi, Toshihiko; Yamamoto, Hirotsugu; Shibuya, Takashi; Yokoyama, Mika; Asakura, Junko
PA Asahi Glass Company Ltd., Japan
SO Eur. Pat. Appl., 29 pp.
CODEN: EPXXDW
DT Patent
LA English
FAN.CNT 2

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE	
PI	EP 899091	A2	19990303	EP 1998-115344	19980814	<--
	EP 899091	A3	20001011			
	EP 899091	B1	20031029			
	R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO					
	JP 11268201	A	19991005	JP 1998-76040	19980324	<--
	JP 3951424	B2	20070801			
	US 6383641	B1	20020507	US 1998-133379	19980813	<--
	JP 11240103	A	19990907	JP 1998-229847	19980814	<--
	JP 3921829	B2	20070530			
	JP 11240104	A	19990907	JP 1998-229848	19980814	<--
	JP 3921830	B2	20070530			
PRAI	JP 1997-220468	A	19970815	<--		
	JP 1997-355588	A	19971224	<--		
	JP 1998-76040	A	19980324	<--		

AB A transparent coated molding product comprises a transparent synthetic resin substrate and at least two layers of transparent cured coatings on at least one part of the surface of the transparent synthetic resin substrate, wherein an inner layer in contact with the outermost layer of the at least two layer of the transparent cured coatings is an abrasion-resistant layer which is a cured material of an active energy ray-curable coating agent (A) containing a polyfunctional compound (a) having at least 2 active energy ray-curable polymerizable functional groups and the outermost layer is a silica layer which is a cured material of a curable coating agent (B) of polysilazane or a curable coating agent (B) containing polysilazane.
IT 220736-33-4
RL: POF (Polymer in formulation); TEM (Technical or engineered material use); USES (Uses)

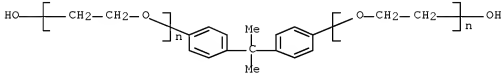
(radiation-curable coating; manufacture of transparent coated moldings having abrasion-resistant coating layer)

RN 220736-33-4 HCAPLUS

CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 1,6-diisocyanatohexane and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly(oxy-1,2-ethanediyl)] (9CI) (CA INDEX NAME)

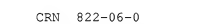
CM 1

CRN 32492-61-8
CMF (C2 H4 O)n (C2 H4 O)n C15 H16 O2
CCI PMS



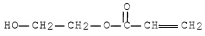
CM 2

CRN 822-06-0
CMF C8 H12 N2 O2



CM 3

CRN 818-61-1
CMF C5 H8 O3



L110 ANSWER 14 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN

AN 1998:143531 HCAPLUS Full-text

DN 128:206024

TI Compositions for coating of aromatic polycarbonate molded products

IN Higuchi, Toshihiko; Kondo, Satoshi; Yamamoto, Hirotsugu; Sanegiri, Yukio

PA Asahi Glass Co., Ltd., Japan

SO Jpn. Kokai Tokkyo Koho, 11 pp.
CODEN: JKXXAF

DT Patent

LA Japanese

FAN.CNT 1

PATENT NO. KIND DATE APPLICATION NO. DATE

PI	JP 10060306	A	19980303	JP 1996-213897	19960813 <--
PRAI	JP 1996-213897		19960813 <--		

AB The compns., forming films with good resistance to scratching and hot bending, comprise (A) multifunctional monomers having ≥3 (meth)acryloyl groups, (B) bifunctional monomers with m.p. ≥0° having 2 (meth)acryloyl groups and urethane linkages, (C) 0.1-30 parts (vs. 100 parts A + B) UV absorbers, and (D) 0.1-20 parts (same as above) photoinitiators. Aromatic polycarbonate molded products coated with the compns. and hot bending process of the coated products are also claimed. Thus, a composition comprising a urethane acrylate (m.p. 28°; prepared by reaction of bisphenol A-ethylene oxide adduct 1, HDI 2, and 2-hydroxyethyl acrylate 2 mol) 50, dipentaerythritol hexaacrylate 50, Me2CHOH 60, BuOAc 60, Et cellosolve 30, 1-hydroxycyclohexyl Ph ketone 5, octyl 3-[3-(2H-benzotriazol-2-yl)-5-tert-butyl-4- hydroxyphenyl]propionate 3, and bis(1,2,2,6,6-pentamethyl-4-piperidyl) sebacate 1 g was applied on an aromatic polycarbonate plate, dried, and irradiated with UV to form a coating showing good scratching resistance, no cracks after bending at 170°, and no changes after 2000-h accelerated weathering.

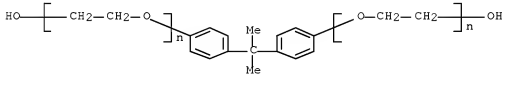
IT 204018-28-0P, Bisphenol A-ethylene oxide adduct-dipentaerythritol acrylate-hexamethylene diisocyanate-2-hydroxyethyl acrylate copolymer
RL: IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(acrylic polyurethane coatings for aromatic polycarbonate molded products with good resistance to hot bending and scratching)

RN 204018-28-0 HCAPLUS

CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 1,6-diisocyanatohexane, α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly(oxy-1,2-ethanediyl)] and 2,2'-[oxybis(methylene)]bis[2-(hydroxymethyl)-1,3-propanediol] 2-propenoate (9CI) (CA INDEX NAME)

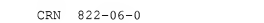
CM 1

CRN 32492-61-8
CMF (C2 H4 O)n (C2 H4 O)n C15 H16 O2
CCI PMS



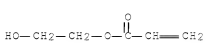
CM 2

CRN 822-06-0
CMF C8 H12 N2 O2



CM 3

CRN 818-61-1
CMF C5 H8 O3

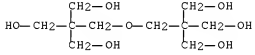


CM 4

CRN 77641-99-7
CMF C10 H22 O7 . x C3 H4 O2

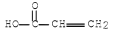
CM 5

CRN 126-58-9
CMF C10 H22 O7



CM 6

CRN 79-10-7
CMF C3 H4 O2



L110 ANSWER 15 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1997:368940 HCAPLUS Full-text
DN 127:18971
TI Electron beam-curable monofunctional urethane (meth)acrylate oligomers and electron beam-curable adhesives containing them
IN Arai, Kazunari; Kato, Shigemiki; Naganuma, Tsutomu; Kawaura, Hirokatsu; Ota, Miwa
PA Toppan Printing Co., Ltd., Japan; Toho Chemical Industry Co., Ltd.
SO Jpn. Kokai Tokkyo Koho, 7 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 09095655	A	19970408	JP 1995-276976	19950930 <--
JP 3367301	B2	20030114		

PRAI JP 1995-276976 19950930 <--

AB Solventless adhesives are prepared by adding alkylene oxides to bisphenols, reacting the diols with diisocyanates, adding hydroxyethyl (meth)acrylate to one end group, and adding an oxime to the other end group. Thus, polypropylene glycol bisphenol A ether-IPDI prepolymer was prepared, treated with 2-hydroxyethyl acrylate and Me Et ketoxime to give an oligomer, mixed (80 parts) with 20 parts nonylphenyloxyethyl acrylate, and used to bond a corona-treated stretched polypropylene (I) film to a corona-treated cast I film.

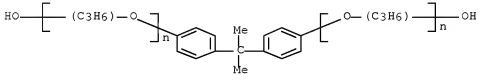
IT 73046-81-8DP, Polypropylene glycol bisphenol A ether-2-hydroxyethyl acrylate-TDI copolymer, reaction products with oximes and monoacrylates 189758-28-9DP, Polyoxypropylene glycol bisphenol A ether-2-hydroxyethyl acrylate-isophorone diisocyanate copolymer, reaction products with oximes and monoacrylates 189758-29-0DP, Polypropylene glycol bisphenol A ether-2-hydroxyethyl acrylate-trimethylhexamethylene diisocyanate copolymer, reaction products with oximes and monoacrylates
RL: IMF (Industrial manufacture); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(electron beam-curable adhesives containing monofunctional urethane (meth)acrylate oligomers for plastic films)

RN 73046-81-8 HCAPLUS

CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 1,3-diisocyanatomethylbenzene and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

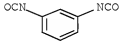
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



CM 2

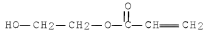
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1— Me

CM 3

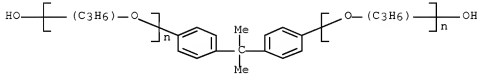
CRN 818-61-1
CMF C5 H8 O3



RN 189758-28-9 HCAPLUS
CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 5-isocyanato-1-(isocyanatomethyl)-1,3,3-trimethylcyclohexane and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

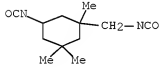
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



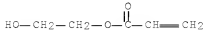
CM 2

CRN 4098-71-9
CMF C12 H18 N2 O2



CM 3

CRN 818-61-1
CMF C5 H8 O3

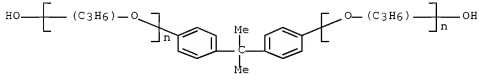


RN 189758-29-0 HCAPLUS

CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 1,6-diisocyanatotrimethylhexane and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

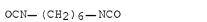
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



CM 2

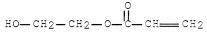
CRN 28679-16-5
CMF C11 H18 N2 O2
CCI IDS



3 (D1—Me)

CM 3

CRN 818-61-1
CMF C5 H8 O3



L110 ANSWER 16 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1997:21116 HCAPLUS Full-text
DN 126:48425
TI Actinic energy ray-curable acrylic polyurethane compositions with improved resistance to stain and scratch, softness, and adhesion
IN Maeda, Seiji; Matsumura, Akira; Ooshita, Akinao
PA Nippon Synthetic Chem Ind, Japan
SO Jpn. Kokai Tokkyo Koho, 7 pp.
CODEN: JKXXAF
DT Patent
LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 08259644	A	19961008	JP 1995-86065	19950317 <--
PRAI	JP 1995-86065		19950317 <--		

AB The compns. comprise (A) urethane acrylates obtained by reacting (A1) bisphenol-type polyols p-H(R1O)nOC6H4CR3R4C6H4O(R2O)mH (R1O, R2O = C2-4 alkylene oxide; R3-4 = H, Me; n + m = 1-20), (A2) polyisocyanates, and (A3) OH-having acrylates, (B) ethylenic unsatd. monomers, (C) photopolymn. initiators, and optionally (D) P compds. Thus, BPX 33 1, IPDI 2, and 2-hydroxyethyl acrylate 2 mol were reacted for 10 h at 70° in PhMe in the presence of dibutyltin dilaurate and 75 parts the obtained urethane acrylate was blended with 25 parts NK Ester AMP 60G and 4 parts 1-hydroxycyclohexyl Ph ketone to give a composition, which was applied to a white paper and exposed to UV to give a test piece with good stain resistance. Its coating on glass plate exhibited good scratch resistance and cross-cut adhesion 96/100. The film exhibited elongation 60%.

IT 184772-15-4P

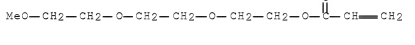
RL: IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(actinic energy ray-curable acrylic polyurethane compns. with improved resistance to stain and scratch, softness, and adhesion)

RN 184772-15-4 HCAPLUS

CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 2-[2-(2-methoxyethoxy)ethoxy]ethyl 2-propenoate, 1,1'-methylenebis[4-isocyanatocyclohexane], α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] and α,α',α''-1,2,3-propanetriyltris[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

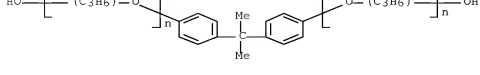
CM 1

CRN 48067-72-7
CMF C10 H18 O5



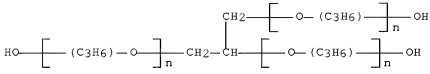
CM 2

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



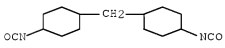
CM 3

CRN 25791-96-2
CMF (C3 H6 O)n (C3 H6 O)n (C3 H6 O)n C3 H8 O3
CCI IDS, PMS



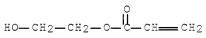
CM 4

CRN 5124-30-1
CMF C15 H22 N2 O2



CM 5

CRN 818-61-1
CMF C5 H8 O3



L110 ANSWER 17 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1995:666279 HCAPLUS Full-text
DN 123:57968
TI Effect of blocking agents on the shock absorbing properties of the films of polyurethane adhesives
AU Roy, Surajit; Kumar, Anil
CS Department of Chemical Engineering, Indian Institute of Technology, Kanpu, 208016, India
SO Polymer Engineering and Science (1995), 35(12), 1046-52
CODEN: PYESAZ; ISSN: 0032-3888
PB Society of Plastics Engineers
DT Journal
LA English
AB Various 4,4-diphenylmethane diisocyanate (MDI) based polyurethane adhesives have been developed using polyethylene glycols (PEG) of different mol. wts. The formulations were modified using different blocking agents to inhibit the isocyanate-moisture reaction. Composite of poly(Me methacrylate) sheets were developed in which these adhesives gave transparent films and their shattering characteristics were tested in a bullet firing machine developed here. The

damaged area was measured and used to characterize the adhesive strength. The mol. weight of the soft segment (diol) and the nature of the blocking agent both were found to affect drastically the urethane film properties.

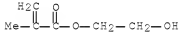
IT 165128-11-0P 165128-13-2P
RL: PRP (Properties); SPN (Synthetic preparation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(effect of polyurethane adhesive composition on the shock absorbing properties of the adhesive-poly(Me methacrylate) films)

RN 165128-11-0 HCAPLUS

CN 2-Propenoic acid, 2-methyl-, 2-hydroxyethyl ester, polymer with 1,1'-methylenebis[4-isocyanatobenzene], 4,4'-(1-methylethylidene)bis[phenol], oxirane and 1,2,3-propanetriol (9CI) (CA INDEX NAME)

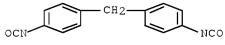
CM 1

CRN 868-77-9
CMF C6 H10 O3



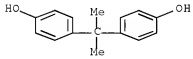
CM 2

CRN 101-68-8
CMF C15 H10 N2 O2



CM 3

CRN 80-05-7
CMF C15 H16 O2

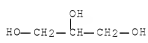


CM 4

CRN 75-21-8
CMF C2 H4 O

CM 5

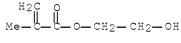
CRN 56-81-5
CMF C3 H8 O3



RN 165128-13-2 HCAPLUS
CN 2-Propenoic acid, 2-methyl-, 2-hydroxyethyl ester, polymer with (chloromethyl)oxirane, 1,1'-methylenebis[4-isocyanatobenzene], 4,4'-(1-methylethylidene)bis[phenol], oxirane and 1,2,3-propanetriol (9CI) (CA INDEX NAME)

CM 1

CRN 868-77-9
CMF C6 H10 O3

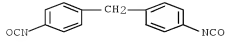


CM 2

CRN 106-89-8
CMF C3 H5 Cl O

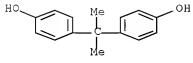
CM 3

CRN 101-68-8
CMF C15 H10 N2 O2



CM 4

CRN 80-05-7
CMF C15 H16 O2

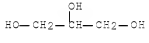


CM 5

CRN 75-21-8
CMF C2 H4 O

CM 6

CRN 56-81-5
CMF C3 H8 O3



L110 ANSWER 18 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1995:475839 HCAPLUS Full-text
DN 123:171395
TI Photopolymerizable resin diluents and compositions thereof
IN Koma, Toshio; Noda, Hironobu
PA Nippon Oils & Fats Co Ltd, Japan
SO Jpn. Kokai Tokkyo Koho, 7 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 07018042	A	19950120	JP 1993-183448	19930630 <--
PRAI JP 1993-183448		19930630 <--		

AB The title compns. comprise (A) diluents composed of polyoxyethylene-polyoxypropylene block copolymer di(meth)acrylate 5-90, (B) ≥1 oligomers selected from urethane (meth)acrylates, epoxy resin (meth)acrylates, and polyester (meth)acrylates 5-90, and (C) photopolymn. initiators 1-8%. Thus,

(a) 50 parts polyoxyethylene-polyoxypropylene dimethacrylate with viscosity 206 cps at 25° was blended with (b) 47 parts urethane acrylate synthesized from 1:2:2 mol bisphenol A ethylene oxide (1:4) adduct, xylylene diisocyanate, and 2-hydroxyethyl acrylate and (c) 3 parts 1-hydroxycyclohexyl Ph ketone, applied to plates of Al, acrylic resins, PVC, and polycarbonates, and exposed to UV irradiation to give test pieces with cross-cut adhesion 100/100 and Erichsen on Al plate 7.1.

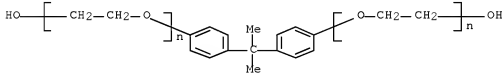
IT 167354-82-7 167354-83-8
RL: MOA (Modifier or additive use); POF (Polymer in formulation); USES (Uses)
(photopolymerizable diluent compns. comprising polyoxyethylene-polyoxypropylene block copolymer di(meth)acrylate)

RN 167354-82-7 HCAPLUS

CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with bis(isocyanatomethyl)benzene, α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly(oxy-1,2-ethanediyl)] and methyloxirane polymer with oxirane bis(2-methyl-2-propenoate) (9CI) (CA INDEX NAME)

CM 1

CRN 32492-61-8
CMF (C2 H4 O)n (C2 H4 O)n C15 H16 O2
CCI PMS

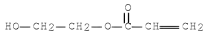


CM 2

CRN 25854-16-4
CMF C10 H8 N2 O2
CCI IDS

CM 3

CRN 818-61-1
CMF C5 H8 O3



CM 4

CRN 87003-89-2
CMF C4 H6 O2 . 1/2 (C3 H6 O . C2 H4 O)x

CM 5

CRN 79-41-4
CMF C4 H6 O2

CM 6

CRN 9003-11-6
CMF (C3 H6 O . C2 H4 O)x
CCI PMS

CM 7

CRN 75-56-9
CMF C3 H6 O

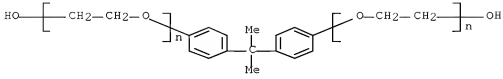
CM 8

CRN 75-21-8
CMF C2 H4 O

RN 167354-83-8 HCAPLUS
CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with bis(isocyanatomethyl)benzene, α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly(oxy-1,2-ethanediyl)], methyloxirane polymer with oxirane bis(2-methyl-2-propenoate), and methyloxirane polymer with oxirane 2-propenoate (9CI) (CA INDEX NAME)

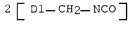
CM 1

CRN 32492-61-8
CMF (C2 H4 O)n (C2 H4 O)n C15 H16 O2
CCI PMS



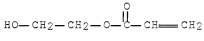
CM 2

CRN 25854-16-4
CMF C10 H8 N2 O2
CCI IDS



CM 3

CRN 818-61-1
CMF C5 H8 O3



CM 4

CRN 87003-89-2
CMF C4 H6 O2 . 1/2 (C3 H6 O . C2 H4 O)x

CM 5

CRN 79-41-4
CMF C4 H6 O2

CM 6

CRN 9003-11-6
CMF (C3 H6 O . C2 H4 O)x
CCI PMS

CM 7

CRN 75-56-9
CMF C3 H6 O

CM 8

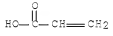
CRN 75-21-8
CMF C2 H4 O

CM 9

CRN 52503-44-3
CMF (C3 H6 O . C2 H4 O)x . 2 C3 H4 O2

CM 10

CRN 79-10-7
CMF C3 H4 O2



CM 11

CRN 9003-11-6
CMF (C3 H6 O . C2 H4 O)x
CCI PMS

CM 12

CRN 75-56-9
CMF C3 H6 O

CM 13

CRN 75-21-8
CMF C2 H4 O

L110 ANSWER 19 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1995:59356 HCAPLUS Full-text
DN 122:215942
TI UV-curable resin compositions for transmission screens and their cured products
IN Nakayama, Kenji; Ozaki, Tooru; Aizawa, Hiroe; Yokoshima, Minoru
PA Nippon Kayaku Kk, Japan
SO Jpn. Kokai Tokkyo Koho, 5 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

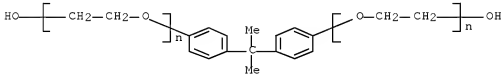
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 06166731	A	19940614	JP 1992-343568	19921201 <--
JP 3372073	B2	20030127		
PRAI JP 1992-343568		19921201 <--		

AB The title compns. contain (A) urethane (meth)acrylates obtained from polyols, organic polyisocyanates, and CH2:CR1CO(OCH2CHR2)nOH (R1 = H, Me; R2 = C1-5 alkyl, aromatic group R3R4R5C6H2OCH2, R6OCH2; R3-R5 = H, Ph, C1-5 alkyl, Br; R6 = C1-10 alkyl; n = 1-5), (B) reactive diluents, and (C) photopolymn. initiators. Cured products of the compns. are also claimed. Thus, 376 parts bisphenol F adduct with 4 mol ethylene oxide was treated with 348 parts TDI and 466.2 parts 2-hydroxy-3-phenoxypropyl acrylate to give an urethane acrylate with refractive index (25°) 1.570, 40 parts of which was mixed with Neomer BA-801 10, Kayarad OPP-2 30, N-vinylcaprolactam 5, Irgacure-184 0.98, and 2,4,6-tribromophenyloxyethyl acrylate 15 parts to give a liquid composition with refractive index (23°) 1.551, which was molded and cured with UV irradiation to give a scratch-resistant Fresnel lens.
IT 162005-48-3DP, polymers with other urethane acrylates and vinyl compds.
RL: IMF (Industrial manufacture); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(preparation of, UV-curable, scratch-resistant Fresnel lenses from)
RN 162005-48-3 HCAPLUS
CN 2-Propenoic acid, 2-hydroxybutyl ester, polymer with 1,3-diisocyanatomethylbenzene and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly(oxy-1,2-ethanediyl)] (9CI) (CA INDEX NAME)

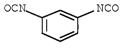
CM 1

CRN 32492-61-8
CMF (C2 H4 O)n (C2 H4 O)n C15 H16 O2
CCI PMS



CM 2

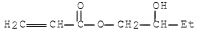
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1—Me

CM 3

CRN 2421-27-4
CMF C7 H12 O3



L110 ANSWER 20 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1992:635153 HCAPLUS Full-text
DN 117:235153
TI Resin compositions with excellent resistance to hydrolysis, corrosion, and hot water
IN Sugawara, Masanori; Kato, Haruhisa; Kobori, Junzo
PA Mitsui Toatsu Kagaku K. K., Japan
SO Jpn. Kokai Tokkyo Koho, 6 pp.

CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 04085319	A	19920318	JP 1990-196372	19900726 <--
	JP 2938162	B2	19990823		
PRAI	JP 1990-196372		19900726 <--		

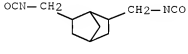
AB The title compns. useful for gel coatings comprise (A) ethylenically unsatd. group-terminated acrylic urethane resins obtained by treating 0.5-1.5 g-equiv OH group-bearing ethylenically unsatd. monomers with 1 g-equiv urethane-modified resins prepared by treating 1 g-equiv glycol components containing bisphenols and 1.1-2.0 g-equiv 2,5- and/or 2,6-diisocyanate methylbicyclo[2,2,1]heptane and (B) ethylenically unsatd. group-containing reactive diluents. Thus, treating 400 g bisphenol A-propylene oxide (3 mol) adduct with 412 g 2,5- and 2,6-diisocyanate methylbicyclo[2,2,1]heptane at 70° for 3 h, adding 260 g hydroxymethyl methacrylate to the reactant, and stirring the mixture at 70° for 3 h gave an acrylic urethane resin. A cured plate prepared from the resin had flexural strength 12.0, tensile strength 7.2, and tensile elongation ratio 3.9.

IT 144473-31-4P 144473-32-5P
RL: PREP (Preparation)
(preparation of, for gel coatings, with good resistance to hydrolysis and corrosion and hot water)

RN 144473-31-4 HCAPLUS
CN 2-Propenoic acid, 2-methyl-, hydroxymethyl ester, polymer with 2,5-bis(isocyanatomethyl)bicyclo[2.2.1]heptane, 2,6-bis(isocyanatomethyl)bicyclo[2.2.1]heptane and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

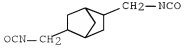
CM 1

CRN 135540-96-4
CMF C11 H14 N2 O2



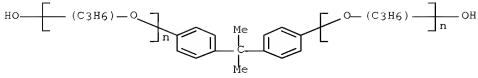
CM 2

CRN 135540-95-3
CMF C11 H14 N2 O2



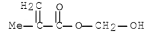
CM 3

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



CM 4

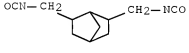
CRN 21982-30-9
CMF C5 H8 O3



RN 144473-32-5 HCAPLUS
CN 2-Propenoic acid, 2-methyl-, hydroxymethyl ester, polymer with 2,5-bis(isocyanatomethyl)bicyclo[2.2.1]heptane, 2,6-bis(isocyanatomethyl)bicyclo[2.2.1]heptane and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly(oxy-1,2-ethanediyl)] (9CI) (CA INDEX NAME)

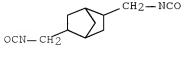
CM 1

CRN 135540-96-4
CMF C11 H14 N2 O2



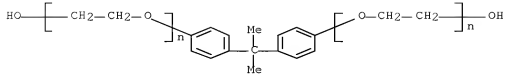
CM 2

CRN 135540-95-3
CMF C11 H14 N2 O2



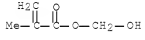
CM 3

CRN 32492-61-8
CMF (C2 H4 O)n (C2 H4 O)n C15 H16 O2
CCI PMS



CM 4

CRN 21982-30-9
CMF C5 H8 O3



L110 ANSWER 21 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1992:450357 HCAPLUS Full-text
DN 117:50357
TI Acrylic polyurethane adhesives for thermal screen printing original papers
IN Okada, Yukio; Sato, Nobuyuki
PA Tokyo Printing Ink Mfg. Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 04031476	A	19920203	JP 1990-134141	19900525 <--
PRAI JP 1990-134141		19900525 <--		

AB The title adhesives, giving screen printing plates with improved drilling properties and printing resistance, comprise compns. of viscosity (P) 100-100,000 cP/25° having 100 parts 100:10-200:5-50 mixts. of urethane diacrylates, epoxy diacrylates, and polyol diacrylates, 1-10 parts photopolymn. initiators, and 1-10 parts tertiary amines. Thus, 35 parts of an acrylate from 1,6-hexanediol-adipic acid copolymer 1, isophorone diisocyanate 2, and 2-hydroxypropyl acrylate 2 mol, 10 parts of an acrylate from 1 mol bisphenol A-epichlorohydrin (1:2) adduct and 2 mol acrylic acid, 10 parts polyethylene glycol diacrylate, 4 parts diethylthioxanthone, and 4 parts N-methyldiethanolamine were mixed to give title adhesive (P 8000 cP), which was applied onto a polyester film, press laminated with a porous support, UV-irradiated then coated with a releasing agent to give a thermal screen printing original paper. The paper was subjected to thermal head to give a printing plate providing images with good appearance after 1000 printings.
IT 142386-25-2P
RL: PREP (Preparation)

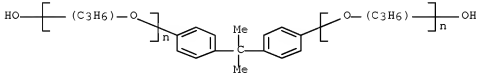
(preparation of, adhesives, photopolymd., containing tertiary amines, for thermal screen printing plates)

RN 142386-25-2 HCAPLUS

CN 2-Propenoic acid, polymer with (chloromethyl)oxirane, α-hydro-ω-hydroxypoly(oxy-1,2-ethanediyl), 2-hydroxypropyl 2-propenoate, 5-isocyanato-1-(isocyanatomethyl)-1,3,3-trimethylcyclohexane and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

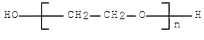
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



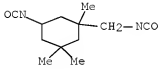
CM 2

CRN 25322-68-3
CMF (C2 H4 O)n H2 O
CCI PMS



CM 3

CRN 4098-71-9
CMF C12 H18 N2 O2



CM 4

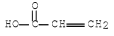
CRN 999-61-1
CMF C6 H10 O3

CM 5

CRN 106-89-8
CMF C3 H5 Cl O

CM 6

CRN 79-10-7
CMF C3 H4 O2



L110 ANSWER 22 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1992:43201 HCAPLUS Full-text
DN 116:43201
TI Radiocurable polyurethanes
IN Nozawa, Fumie; Hara, Yasuo; Igarashi, Katsutoshi; Zimmerman, John M.; Bishop, Timothy E.
PA DeSoto, Inc., USA; Japan Synthetic Rubber Co., Ltd.
SO Jpn. Kokai Tokkyo Koho, 11 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

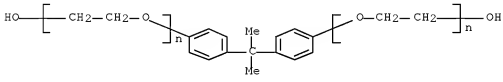
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 03199227	A	19910830	JP 1989-336170	19891225 <--
PRAI JP 1989-336170		19891225 <--		

AB The title resins are prepared from polyisocyanates, polyols, and ≥2 esters CH2:CR1CO2R2 [R1 = H, Me; R2 = (CxH2xO)m(COCyH2yO)nH (x = 1-30, y = 3-8, m = 1-20, n = 0-20)]. Thus, 4,4'-dicyclohexomethane diisocyanate (I)-Nippollan 4009-DA-350F-Placcel FA-5-glycerin copolymer was treated with a I-2-hydroxyethyl acrylate adduct to give a prepolymer which was coated on a polyester film and cured by electron beams.
IT 137843-72-2
RL: TEM (Technical or engineered material use); USES (Uses)
(coatings, radiocurable)
RN 137843-72-2 HCAPLUS
CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 2,4-diisocyanato-1-methylbenzene, 1,2-ethanediol, α-hydro-ω-hydroxypoly(oxy-1,4-

butanediyl), α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly(oxy-1,2-ethanediyl)] and α-(1-oxo-2-propenyl)-ω-hydroxypoly(oxy-1,2-ethanediyl) (9CI) (CA INDEX NAME)

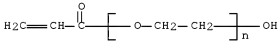
CM 1

CRN 32492-61-8
CMF (C2 H4 O)n (C2 H4 O)n C15 H16 O2
CCI PMS



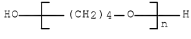
CM 2

CRN 26403-58-7
CMF (C2 H4 O)n C3 H4 O2
CCI PMS



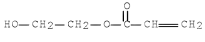
CM 3

CRN 25190-06-1
CMF (C4 H8 O)n H2 O
CCI PMS



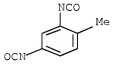
CM 4

CRN 818-61-1
CMF C5 H8 O3



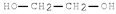
CM 5

CRN 584-84-9
CMF C9 H6 N2 O2



CM 6

CRN 107-21-1
CMF C2 H6 O2



L110 ANSWER 23 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1991:165900 HCAPLUS Full-text
DN 114:165900
TI UV-curable pressure-sensitive adhesives for silicon wafer dicing
IN Kuroda, Hideo; Nakahara, Masaki; Suzuki, Naofumi
PA Bando Chemical Industries, Ltd., Japan; Daiichi Kogyo Seiyaku Co., Ltd.
SO Jpn. Kokai Tokkyo Koho, 12 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

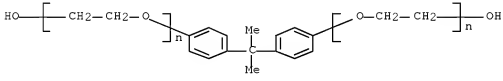
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 02218783	A	19900831	JP 1989-40734	19890220 <--
JP 07000772	B	19950111		
PRAI JP 1989-40734		19890220 <--		

AB The title adhesives comprise 100 parts elastic polymers, 5-150 parts urethane-containing UV-curable (meth)acrylic esters, UV-curable (meth)acrylic esters, and polyisocyanates. Thus, 1:2:2 (mol) [1:4 (mol) bisphenol A-ethylene oxide adduct]-2-hydroxyethyl acrylate-xylylene diisocyanate copolymer (I; average mol. weight 1010) 10, 100:30:70 (mol) ethylene glycol-sebacic acid-terephthalic acid copolymer 30, a tackifier 15, trimethylolpropane triacrylate 30, benzoin 5, Sumidur L 3, Aerosil 2, and 1:4 MEK-toluene mixture 70 parts were blended, applied 10 μm (dry) on a releasing paper, dried 1 min at 120°, and transfered on a PVC film to give an adhesive sheet having peel strength 520 and 15 g/25 mm, as prepared and after being exposed to UV irradiation, uniform expanding ability (for easy to release wafers after cutting), and no residual adhesive on the cut wafers, vs. 515, 10, nonuniform expanding, and with residual adhesive, resp., for a control adhesive prepared without I.
IT 133126-16-6
RL: USES (Uses)
(UV-curable adhesives containing, for silicon wafer dicing)

RN 133126-16-6 HCAPLUS
CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with bis(isocyanatomethyl)benzene and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly(oxy-1,2-ethanediyl)] (9CI) (CA INDEX NAME)

CM 1

CRN 32492-61-8
CMF (C2 H4 O)n (C2 H4 O)n C15 H16 O2
CCI PMS

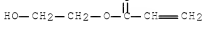


CM 2

CRN 25854-16-4
CMF C10 H8 N2 O2
CCI IDS

CM 3

CRN 818-61-1
CMF C5 H8 O3



L110 ANSWER 24 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1989:644278 HCAPLUS Full-text
DN 111:244278
TI Electrophotographic organic photoreceptors with photosensitive layer containing visible light-hardenable resin as binder
IN Tanaka, Masafumi
PA Mita Industrial Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 4 pp.

CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 01116553	A	19890509	JP 1987-273878	19871029 <--
PRAI JP 1987-273878		19871029 <--		

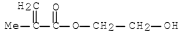
AB Electrophotog. organic photoreceptors are prepared by forming, on a conductive substrate, a single laminated photosensitive layer comprising a charge-generating substance, a charge-transporting substance, and a binder resin from a visible light-hardenable resin. The photoreceptors exhibit good abrasion resistance, solvent resistance, and sensitivity. Thus, an Al substrate was coated with a composition containing a urethane prepolymer obtained from 2,2'-bis(p-hydroxyphenyl)propane, propylene oxide, and diphenylmethane 4,4'-diisocyanate, dihydroxyethyl methacrylate, benzil, α-naphthil, dimethylaminoethyl methacrylate, N-ethylcarbazole-3- carbaldehyde diphenylhydrazone, and dibromoanthanthrone and then irradiated with visible light (420 nm) to give a photoreceptor showing high sensitivity.

IT 123991-14-0
RL: USES (Uses)
(binders, for electrophotog. photoreceptors)

RN 123991-14-0 HCAPLUS
CN 2-Propenoic acid, 2-methyl-, 2-hydroxyethyl ester, polymer with 1,1'-methylenebis[4-isocyanatobenzene], 4,4'-(1-methylethylidene)bis[phenol] and methyloxirane (9CI) (CA INDEX NAME)

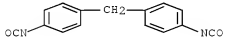
CM 1

CRN 868-77-9
CMF C6 H10 O3



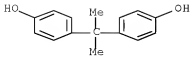
CM 2

CRN 101-68-8
CMF C15 H10 N2 O2



CM 3

CRN 80-05-7
CMF C15 H16 O2



CM 4

CRN 75-56-9
CMF C3 H6 O

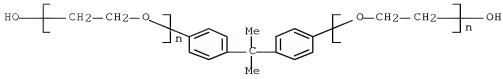
L110 ANSWER 25 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1989:155742 HCAPLUS Full-text
DN 110:155742
TI Beads of hot-melt adhesives for liquid-crystal devices
IN Oka, Koichiro
PA Toray Industries, Inc., Japan
SO Jpn. Kokai Tokkyo Koho, 7 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 63218780	A	19880912	JP 1987-50679	19870305 <--
PRAI JP 1987-50679		19870305 <--		

AB The title adhesives comprise spherical particles [average diameter (d) 0.5-500 μm] of unsatd. compds. Adding 8 g 8% aqueous poly(vinyl alc.) over 4 min to 10 g 15% CHCl3 solution of N,N'-[methylenebis(3-methyl-m-phenylene)]bismaleimide gave an emulsion which was diluted with 10 g water and heated to 60° to give spherical particles with d 18 μm. Glass plates were bonded by these particles with pressing for 2 h at 190° with high peel strength.
IT 119923-09-0
RL: TEM (Technical or engineered material use); USES (Uses)
(adhesives, hot-melt, manufacture of beads)
RN 119923-09-0 HCAPLUS
CN 2-Propenoic acid, polymer with 1,3-diisocyanatomethylbenzene and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly(oxy-1,2-ethanediyl)] (9CI) (CA INDEX NAME)

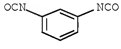
CM 1

CRN 32492-61-8
CMF (C2 H4 O)n (C2 H4 O)n C15 H16 O2
CCI PMS



CM 2

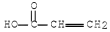
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1—Me

CM 3

CRN 79-10-7
CMF C3 H4 O2



L110 ANSWER 26 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1989:96510 HCAPLUS Full-text
DN 110:96510
TI Water-resistant resin moldings containing glass flakes
IN Takiyama, Eiichiro; Arai, Michiaki; Sakimoto, Seiichiro
PA Showa Highpolymer Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 5 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 63165109	A	19880708	JP 1986-309182	19861227 <--
PRAI JP 1986-309182		19861227 <--		

AB Water-resistant moldings, useful for bathtubs, washbasins, and tiles, comprise gel coatings, glass flake-filled, thermosetting resin layers, and casting resin layers. A release agent-treated glass plate was coated with 0.5 mm mixture of propoxylated bisphenol A-fumaric acid copolymer (I) 100, SiO2 4, and peroxide 1.5 parts, cured 30 min at 60°, coated with 1 mm mixture of I 100, glass flakes (CF-18) 50, peroxide 16, and additives 4 parts, cured 30 min at 60°, covered with a cast 10-mm layer of I 100, Al(OH)3 70, H-110 140, and

peroxide 1 part, and cured at 60° for 2 h and 80° for 2 h to give a laminate with good resistance to boiling water.

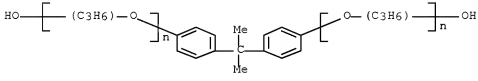
IT 119357-59-4
RL: USES (Uses)
(laminates, glass flake-filled, water-resistant)

RN 119357-59-4 HCAPLUS

CN 2-Propenoic acid, 2-methyl-, polymer with (chloromethyl)oxirane, 5-isocyanato-1-(isocyanatomethyl)-1,3,3-trimethylcyclohexane, 4,4'-(1-methylethylidene)bis[phenol] and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

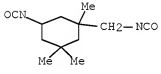
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



CM 2

CRN 4098-71-9
CMF C12 H18 N2 O2



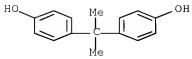
CM 3

CRN 106-89-8
CMF C3 H5 Cl O

CM 4

CRN 80-05-7

CMF C15 H16 O2



CM 5

CRN 79-41-4
CMF C4 H6 O2

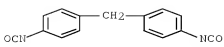
L110 ANSWER 27 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1988:530258 HCAPLUS Full-text
DN 109:130258
TI Curable resin compositions
IN Takiyama, Eichiro; Arai, Michiaki; Arai, Takao
PA Showa Highpolymer Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 63092633	A	19880423	JP 1986-237202	19861007 <--
	JP 04011567	B	19920228		
PRAI	JP 1986-237202		19861007 <--		

AB Compns. with good hardness and strength, useful in adhesives, coatings, moldings, fiber-reinforced plastics, etc., contain polyols (prepared from polyphenols or novolaks and monoepoxides), reaction products of epoxides with (meth)acrylic acid, and diisocyanates. A styrene solution of bisphenol A-Ph glycidyl ether (I) copolymer was heated 5 h at 60° with 2,4-TDI and mixed with I-methacrylic acid copolymer and Hardener 328E to give a cured product with flexural strength 15.7 kg/mm2, Charpy impact strength 2.6 kg-cm/cm2, heat distortion temperature 116°, and Rockwell hardness M-116.
IT 116543-20-5P
RL: PREP (Preparation)
(manufacture of, with good strength and hardness)
RN 116543-20-5 HCAPLUS
CN 2-Propenoic acid, 2-methyl-, polymer with 1,1'-methylenebis[4-isocyanatobenzene], 4,4'-(1-methylethylidene)bis[phenol] and methyloxirane (9CI) (CA INDEX NAME)

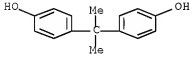
CM 1

CRN 101-68-8
CMF C15 H10 N2 O2



CM 2

CRN 80-05-7
CMF C15 H16 O2



CM 3

CRN 79-41-4
CMF C4 H6 O2

CM 4

CRN 75-56-9
CMF C3 H6 O

L110 ANSWER 28 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1988:530257 HCAPLUS Full-text
DN 109:130257
TI Curable polyurethane compositions
IN Takiyama, Eichiro; Arai, Michiaki; Arai, Takao
PA Showa Highpolymer Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 8 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 63092632	A	19880423	JP 1986-237201	19861007 <--
	JP 04011566	B	19920228		
PRAI	JP 1986-237201		19861007 <--		

AB Compns. with good hardness and strength, useful in adhesives, coatings, moldings, fiber-reinforced plastics, etc., contain polyols (prepared from polyphenols or novolaks and epoxides), epoxy resin (meth)acrylates bearing OH-groups, and diisocyanates. A styrene solution of bisphenol A-Ph glycidyl ether copolymer was heated 5 h at 60° with 2,4-TDI and mixed with Epikote 827 methacrylate and Hardener 328E to give a cured product with tensile strength 8.1 kg/mm2, flexural strength 16.9 kg/mm2, flexural modulus 440 kg/mm2, Charpy impact strength 4.1 kg-cm/cm2, heat distortion temperature 132°, and Rockwell hardness M-115.

IT 116543-28-3P

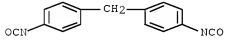
RL: PREP (Preparation)
(manufacture of, with high strength and hardness)

RN 116543-28-3 HCAPLUS

CN Phenol, 4,4'-(1-methylethylidene)bis-, polymer with DEN 431 2-methyl-2-propenoate, 1,1'-methylenebis[4-isocyanatobenzene] and methyloxirane (9CI) (CA INDEX NAME)

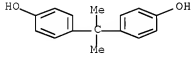
CM 1

CRN 101-68-8
CMF C15 H10 N2 O2



CM 2

CRN 80-05-7
CMF C15 H16 O2



CM 3

CRN 75-56-9
CMF C3 H6 O

CM 4

CRN 79620-43-2
CMF C4 H6 O2 . x Unspecified

CM 5

CRN 37348-52-0
CMF Unspecified
CCI PMS, MAN

*** STRUCTURE DIAGRAM IS NOT AVAILABLE ***

CM 6

CRN 79-41-4
CMF C4 H6 O2

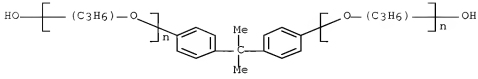
L110 ANSWER 29 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1987:197568 HCAPLUS Full-text
DN 106:197568
TI Lining sheets for underwater application
IN Saito, Tsutomu; Watanabe, Masao
PA Three Bond Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 4 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 61297122	A	19861227	JP 1985-137972	19850626 <--
PRAI JP 1985-137972		19850626 <--		

AB Lining sheets comprising a UV-transmissible plastic sheet (e.g. PET polyester) laminated on a water-insol. UV-curable resin-impregnated glass cloth are placed on (with glass cloth side toward) a place (underwater) to be protected, the sheet are pressed to expel water, and then irradiated by UV to cure the resin. The process affords rapid curing, uniform finishing for a large area, and good productivity.
IT 73046-81-8
RL: USES (Uses)
(UV-curable, impregnated in glass cloth and laminated on PET polyester film, for underwater lining sheets)
RN 73046-81-8 HCAPLUS
CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 1,3-diisocyanatomethylbenzene and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

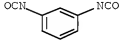
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



CM 2

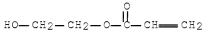
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1— Me

CM 3

CRN 818-61-1
CMF C5 H8 O3



L110 ANSWER 30 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1986:26804 HCAPLUS Full-text
DN 104:26804
OREF 104:4301a,4304a
TI Solder masks
IN Lindley, Andrew Arthur
PA Imperial Chemical Industries PLC, UK
SO Eur. Pat. Appl., 28 pp.
CODEN: EPXXDW
DT Patent
LA English
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	EP 145345	A2	19850619	EP 1984-307991	19841119 <--

EP 145345 A3 19860730
EP 145345 B1 19890208
R: AT, BE, CH, DE, FR, GB, IT, LI, NL, SE
AT 40756 T 19890215 AT 1984-307991 19841119 <--
JP 60144734 A 19850731 JP 1984-256580 19841206 <--
PRAI GB 1983-32520 A 19831206 <--
GB 1984-14438 A 19840606 <--
EP 1984-307991 A 19841119 <--

AB A photopolymerizable composition for the preparation of solder masks comprises an olefinically unsatd. aromatic/aldehyde oligomer and/or a vinylurethane, a polymer binder, and a photoinitiator system. Thus, a photopolymerizable composition comprised of an aromatic/aldehyde oligomer prepared from di-Ph ether, paraformaldehyde, and methacrylic acid 57.2, Bu acrylate-Me methacrylate copolymer 38.1, 2,6-di-tert-butyl-4-methylphenol 0.05, 2-dimethylaminoethyl benzoate 2.3, and 4-benzoyl-4'-methyldiphenyl sulfide 2.3 parts dissolved in an organic solvent was coated on a polyester film support, dried to give a tack-free solid layer (40 μ thick), laminated on a polyethylene support film at 60°, hot pressed onto the Cu surface of a circuit board, exposed to UV through a step wedge, the support film removed, and developed in 1,1,1-trichloroethane to show a step wedge number of 11.

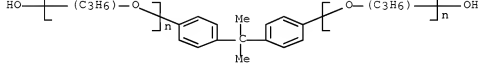
IT 99631-02-4
RL: USES (Uses)
(photopolymerizable compns. containing aromatic compound-aldehyde oligomer and
polymer binder and photoinitiator and, for preparation of soldering masks)

RN 99631-02-4 HCAPLUS

CN 2-Propenoic acid, 2-methyl-, monoester, with 1,2-propanediol, polymer with 1,6-diisocyanatohexane and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

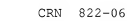
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



CM 2

CRN 822-06-0
CMF C8 H12 N2 O2



CM 3

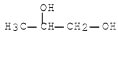
CRN 27813-02-1
CMF C7 H12 O3
CCI IDS

CM 4

CRN 79-41-4
CMF C4 H6 O2

CM 5

CRN 57-55-6
CMF C3 H8 O2



L110 ANSWER 31 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1984:408331 HCAPLUS Full-text
DN 101:8331
OREF 101:1413a,1416a
TI Electron beam curable adhesive
PA Mitsubishi Rayon Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 5 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

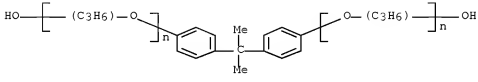
	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 58174475	A	19831013	JP 1982-58448	19820408 <--
	JP 02008631	B	19900226		
PRAI	JP 1982-58448		19820408 <--		

AB The title adhesives, with low radiation dose requirements, contain polyurethane acrylates (number-average mol. weight 500-20,000) 10-70, polyol polyacrylates 10-70, vinyl monomers 20-70, and unsatd. P compds. 0.05-10 parts. Thus, mixing 40 parts resin [90387-21-6] (mol. weight 3000) from 2-hydroxypropyl acrylate 2, bisphenol A polypropylene glycol ether (Adeka BPX 11) 1, and isophorone diisocyanate 20 mol with pentaerythritol tetraacrylate [4986-89-4] 15, tetrahydrofurfuryl acrylate [2399-48-6] 40, and 2-(acryloyloxy)ethyl acid phosphate [32120-16-4] 5 parts gave an adhesive curable by 20 Mrad 300-kV electron beams.
IT 90387-21-6
RL: TEM (Technical or engineered material use); USES (Uses)
(adhesives, electron beam-curable)
RN 90387-21-6 HCAPLUS
CN 2-Propenoic acid, 2-hydroxypropyl ester, polymer with 5-isocyanato-1-

(isocyanatomethyl)-1,3,3-trimethylcyclohexane and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

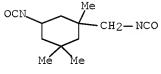
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



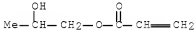
CM 2

CRN 4098-71-9
CMF C12 H18 N2 O2



CM 3

CRN 999-61-1
CMF C6 H10 O3



L110 ANSWER 32 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1981:570597 HCAPLUS Full-text
DN 95:170597
OREF 95:28533a,28536a
TI Radically curable adhesive compositions
PA Toyobo Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 9 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1
PATENT NO. KIND DATE APPLICATION NO. DATE

PI	JP 56062866	A	19810529	JP 1979-138856	19791026 <--
	JP 61055554	B	19861128		
PRAI	JP 1979-138856	A	19791026 <--		

AB Adhesives for metals contain urethane-modified acrylates, epoxy acrylates, and other comonomers. Thus, styrene 375, bisphenol A-(11 mols) propylene oxide adduct 866, hydroquinone 0.08, and 2,4-tolylene diisocyanate 348 parts were heated at 80° for 2 h to give a urethane prepolymer containing terminal isocyanate groups, mixed with 286 parts ethylene glycol monomethacrylate, heated at 80° for 3 h to give a resin (I) [74576-11-7], which was mixed with an epoxy methacrylate (II) [61970-25-0] at resin ratio 80:20 and used to bond steel with adhesion 120 kg/cm2, compared with 87 kg/m2 or 93 kg/cm2 for bonding only with I or II, resp. The II was prepared by heating Epikote 834 470, methacrylic acid 181, hydroquinone 0.06, and C6H3CH2Me3NCl 1.19 parts at 120° to >95% conversion and dissolving in styrene to styrene content 35%.

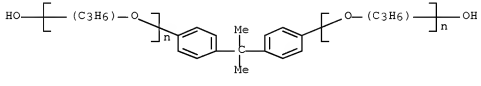
IT 74576-11-7
RL: TEM (Technical or engineered material use); USES (Uses)
(adhesives, containing epoxy acrylates, for metals)

RN 74576-11-7 HCAPLUS

CN 2-Propenoic acid, 2-methyl-, 2-hydroxyethyl ester, polymer with 2,4-diisocyanato-1-methylbenzene and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

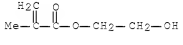
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



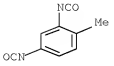
CM 2

CRN 868-77-9
CMF C6 H10 O3



CM 3

CRN 584-84-9
CMF C9 H6 N2 O2



L110 ANSWER 33 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1981:570365 HCAPLUS Full-text
DN 95:170365
OREF 95:28497a,28500a
TI Radically curable adhesive compositions
PA Toyobo Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 9 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 56062868	A	19810529	JP 1979-140116	19791029 <--
JP 61055555	B	19861128		
PRAI JP 1979-140116	A	19791029 <--		

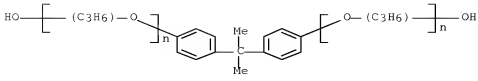
AB Adhesives for metals contain a urethane-modified acrylate, an epoxy acrylate, a comonomer, and an epoxy compound Thus, styrene 875, 1:11 bisphenol A-propylene oxide adduct 866, hydroquinone 0.08, and 2,4-tolylene diisocyanate 848 parts were heated at 80° for 2 h to give a urethane prepolymer containing terminal isocyanate groups, mixed with 286 parts ethylene glycol monomethacrylate, heated at 80° for 8 h to give a resin [79412-24-1], mixed with Epikote 834 methacrylate (I) [61970-25-0] at resin ratio 50:50, mixed (100 parts) with 10 parts Epikote 1004 (II) [25068-38-6], and used to bond polyester canvas to steel without sandblasting with peeling strength 1.5 kg/cm, compared with 0.7 kg/cm for using an adhesive containing no II. I was prepared by heating Epikote 834 470, methacrylic acid 181, hydroquinone 0.06, and Me3C6H5CH2NCl 1.19 parts at 120° to >95% conversion and dissolving in styrene.

IT 79412-24-1
RL: USES (Uses)
(adhesives, containing epoxy acrylates and epoxy resins, for bonding of steel to polyester fibers)

RN 79412-24-1 HCAPLUS
CN 2-Propenoic acid, 2-methyl-, 2-hydroxyethyl ester, polymer with 1,3-diisocyanatomethylbenzene and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

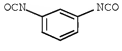
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



CM 2

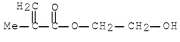
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1—Me

CM 3

CRN 868-77-9
CMF C6 H10 O3



L110 ANSWER 34 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1980:645508 HCAPLUS Full-text
DN 93:245508
OREF 93:39249a,39252a
TI Dental compositions comprising a selected vinyl urethane prepolymer
IN Denyer, Robert; Fortuin, Michael Stanley
PA Imperial Chemical Industries Ltd., UK
SO Eur. Pat. Appl., 31 pp.
CODEN: EPXXDW
DT Patent
LA English
FAN.CNT 2

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	EP 12535	A1	19800625	EP 1979-302671	19791122 <--
	EP 12535	B1	19830119		
	R: AT, BE, CH, DE, FR, GB, IT, LU, NL, SE				
	AT 2251	T	19830215	AT 1979-302671	19791122 <--
	ZA 7906404	A	19810325	ZA 1979-6404	19791126 <--
	NO 7903885	A	19800619	NO 1979-3885	19791129 <--
	NO 151224	B	19841126		
	NO 151224	C	19850306		

	IL 58835	A	19830331	IL 1979-58835	19791130	<--
	AU 7953393	A	19800626	AU 1979-53393	19791203	<--
	AU 531536	B2	19830825			
	US 4457818	A	19840703	US 1979-100039	19791204	<--
	CA 1148294	A1	19830614	CA 1979-341275	19791205	<--
	HU 27565	A2	19831028	HU 1979-IE900	19791210	<--
	HU 184134	B	19840730			
	FI 7903885	A	19800619	FI 1979-3885	19791212	<--
	FI 71482	B	19861010			
	FI 71482	C	19870119			
	ES 486975	A1	19801001	ES 1979-486975	19791217	<--
	DK 7905392	A	19800619	DK 1979-5392	19791218	<--
	DK 155635	B	19890501			
	DK 155635	C	19890925			
	JP 55083706	A	19800624	JP 1979-163664	19791218	<--
	JP 02010801	B	19900309			
	US 4689015	A	19870825	US 1985-789360	19851022	<--
PRAI	GB 1978-48967	A	19781218	<--		
	GB 1979-11709	A	19790404	<--		
	EP 1979-302671	A	19791122	<--		
	US 1979-100039	A1	19791204	<--		
	US 1984-598209	A1	19840409	<--		

OS MARPAT 93:245508

AB Dental compns., suitable as fissure sealants, glazes, bonding agents or adhesives, are a mixture of a vinyl urethane prepolymer, comonomer, and, a visible light cure catalyst comprising an organic amine and α-diketone. A 2,2-bis(p-hydroxyphenyl)propane and propylene oxide condensate (1:2) dissolved in CH_2Cl_2 was added to a CH_2Cl_2 solution of hexamethylene diisocyanate. Dibutyltin dilaurate was added as catalyst. To the mixture was added hydroxypropyl methacrylate in CH_2Cl_2 and refluxed. The vinyl urethane prepolymer was obtained and incorporated into a dental composition: vinyl urethane 13.0, ethylene glycol dimethacrylate 10.65, diethylaminoethyl methacrylate 0.1203, and camphorquinone 0.1775 g. Properties were given for the resulting polymer.

IT 75836-01-0P

RL: PREP (Preparation)
(preparation of, as prepolymer for dental compns.)

RN 75836-01-0 HCAPLUS

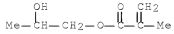
CN 2-Propenoic acid, 2-methyl-, 2-hydroxy-1-methylethyl ester, polymer with 1,6-diisocyanatohexane, 2-hydroxypropyl 2-methyl-2-propenoate, 4,4'-(1-methylethylidene)bis[phenol] and methyloxirane (9CI) (CA INDEX NAME)

CM 1

CRN 4664-49-7
CMF C7 H12 O3

CM 2

CRN 923-26-2
CMF C7 H12 O3

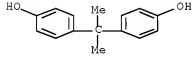


CM 3

CRN 822-06-0
CMF C8 H12 N2 O2

CM 4

CRN 80-05-7
CMF C15 H16 O2



CM 5

CRN 75-56-9
CMF C3 H6 O

L110 ANSWER 35 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1980:496224 HCAPLUS Full-text
DN 93:96224
OREF 93:15447a,15450a
TI Copolymerizable molding composition based on unsaturated polyurethanes
IN Von Harpe, Hannes; Bottenbruch, Ludwig; Peltzer, Bernd; Morbitzer, Leo; Korber, Helmut; Schulz-Walz, Hansjochen
PA Bayer A.-G., Fed. Rep. Ger.
SO Ger. Offen., 40 pp.
CODEN: GWXXBX
DT Patent
LA German
FAN.CNT 1
PATENT NO. KIND DATE APPLICATION NO. DATE

PI	DE 2851340	A1	19800604	DE 1978-2851340	19781128 <--
	DE 2851340	C2	19900726		
	JP 55075416	A	19800606	JP 1978-161298	19781228 <--
PRAI	DE 1978-2851340	A	19781128 <--		

AB Impact-resistant molding compns. contain vinyl monomers, polyurethane methacrylates, and rubbers with glass temperature −90° to +10° (urethane, ethylene-vinyl acetate) and particle diameter 0.1-100.0 μ as a second phase. Thus, 522 g 2,4-TDI containing 0.2 g hydroquinone is mixed at 80° with 688 g (2 mol) propoxylated bisphenol A in 652 g styrene and 260 g hydroxyethyl methacrylate, diluted to 50% solids with styrene, mixed with 12% 55:45 ethylene vinyl acetate rubber and Bz2O2, and cured 3 h at 75° and 15 h at 90° to give a molding with impact strength 33 kJ/m2 and Martens heat distortion temperature 82°, compared with 18 and 82°, resp., with no rubber.

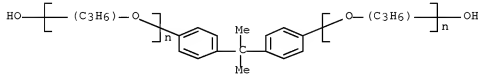
IT 74576-11-7 74576-12-8
RL: USES (Uses)
(blends with rubbers, impact-resistant)

RN 74576-11-7 HCAPLUS

CN 2-Propenoic acid, 2-methyl-, 2-hydroxyethyl ester, polymer with 2,4-diisocyanato-1-methylbenzene and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

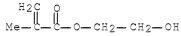
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



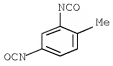
CM 2

CRN 868-77-9
CMF C6 H10 O3



CM 3

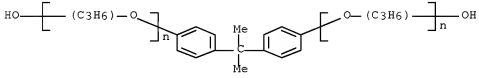
CRN 584-84-9
CMF C9 H6 N2 O2



RN 74576-12-8 HCAPLUS
CN 2-Propenoic acid, 2-methyl-, 2-hydroxyethyl ester, polymer with 1,1'-methylenebis[isocyanatobenzene] and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

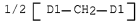
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



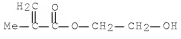
CM 2

CRN 26447-40-5
CMF C15 H10 N2 O2
CCI IDS



CM 3

CRN 868-77-9
CMF C6 H10 O3



L110 ANSWER 36 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1980:427921 HCAPLUS Full-text
DN 93:27921
OREF 93:4681a,4684a
TI Radiation-curable resin compositions
IN Tsunoda, Juzo; Meiwa, Yoshihei; Minakata, Masaaki
PA Kao Soap Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 18 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 55016063	A	19800204	JP 1978-90118	19780724 <--
	JP 60050205	B	19851107		
PRAI	JP 1978-90118	A	19780724 <--		

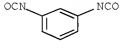
AB UV-curable coatings and inks were prepared from acrylic polyurethanes such as acrylic acid-adipic acid-bisphenol A-2-hydroxyethyl acrylate-propylene oxide-tolylene diisocyanate copolymer (I) [73920-28-2], acrylic acid-adipic acid-bisphenol A-glycidyl acrylate-2-hydroxyethyl acrylate-propylene oxide-tolylene diisocyanate copolymer [73930-15-1], etc. Thus, 2 mols 1:2 (molar) bisphenol A-propylene oxide adduct and 1.01 mols adipic acid were heated under N at 220° for 8 h to acid number <8 and dehydrated in vacuo for 1 h to give a polyester glycerol having acid number 3.2. The product (1 mol) was mixed with 1 mol acrylic acid, 4.5 g p-toluenesulfonic acid, and 0.23 g hydroquinone; heated at 135° for 13 h to give an acrylate; mixed (1.05 mol) with 1.01 mol 2-hydroxyethyl acrylate (II); dehydrated at 90° in vacuo; cooled to 65°; mixed with 1 mol TDI; heated at 65-80° for 1 h and at 125-30° for 5 h to give an acrylic urethane; mixed (60 parts) with 40 parts II and 5 parts benzoin iso-Bu ether; coated on art paper printed with a red ink; and irradiated with UV to form a I coating with curing time 0.25 s.

IT 73920-36-2 73930-18-4
RL: TEM (Technical or engineered material use); USES (Uses)
(coatings, on glass, UV-curable)

RN 73920-36-2 HCAPLUS
CN 2-Propenoic acid, polymer with 1,3-diisocyanatomethylbenzene, 2-hydroxyethyl 2-propenoate, 4,4'-(1-methylethylidene)bis[phenol], methyloxirane and (tetrahydro-2-furanyl)methyl 2-propenoate (9CI) (CA INDEX NAME)

CM 1

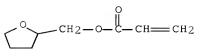
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1— Me

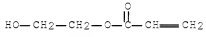
CM 2

CRN 2399-48-6
CMF C8 H12 O3



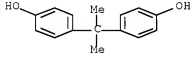
CM 3

CRN 818-61-1
CMF C5 H8 O3



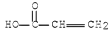
CM 4

CRN 80-05-7
CMF C15 H16 O2



CM 5

CRN 79-10-7
CMF C3 H4 O2



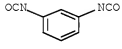
CM 6

CRN 75-56-9
CMF C3 H6 O

RN 73930-18-4 HCAPLUS
CN 2-Propenoic acid, polymer with 1,3-diisocyanatomethylbenzene, 2-hydroxyethyl 2-propenoate, 4,4'-(1-methylethylidene)bis[phenol], methyloxirane and oxiranylmethyl 2-propenoate (9CI) (CA INDEX NAME)

CM 1

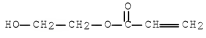
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1—Me

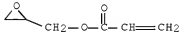
CM 2

CRN 818-61-1
CMF C5 H8 O3



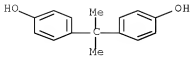
CM 3

CRN 106-90-1
CMF C6 H8 O3



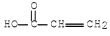
CM 4

CRN 80-05-7
CMF C15 H16 O2



CM 5

CRN 79-10-7
CMF C3 H4 O2



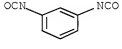
CM 6

CRN 75-56-9
CMF C3 H6 O

IT 73920-33-9 73920-34-0 73930-17-3
RL: TEM (Technical or engineered material use); USES (Uses)
(coatings, on paper, UV-curable)
RN 73920-33-9 HCAPLUS
CN 2-Propenoic acid, polymer with 1,3-diisocyanatomethylbenzene, 2-hydroxyethyl 2-propenoate, 2-hydroxypropyl 2-propenoate, 4,4'-(1-methylethylidene)bis[phenol] and methyloxirane (9CI) (CA INDEX NAME)

CM 1

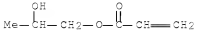
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1— Me

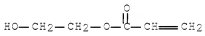
CM 2

CRN 999-61-1
CMF C6 H10 O3



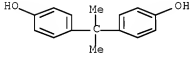
CM 3

CRN 818-61-1
CMF C5 H8 O3



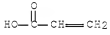
CM 4

CRN 80-05-7
CMF C15 H16 O2



CM 5

CRN 79-10-7
CMF C3 H4 O2



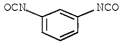
CM 6

CRN 75-56-9
CMF C3 H6 O

RN 73920-34-0 HCAPLUS
CN 2-Propenoic acid, polymer with 1,3-diisocyanatomethylbenzene, 2-hydroxyethyl 2-propenoate, 4,4'-(1-methylethylidene)bis[phenol] and methyloxirane (9CI) (CA INDEX NAME)

CM 1

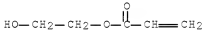
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1—Me

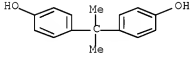
CM 2

CRN 818-61-1
CMF C5 H8 O3



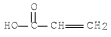
CM 3

CRN 80-05-7
CMF C15 H16 O2



CM 4

CRN 79-10-7
CMF C3 H4 O2



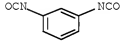
CM 5

CRN 75-56-9
CMF C3 H6 O

RN 73930-17-3 HCAPLUS
CN 2-Propenoic acid, 2-methyl-, polymer with 1,3-diisocyanatomethylbenzene, 2-hydroxyethyl 2-methyl-2-propenoate, 2-hydroxyethyl 2-propenoate, 4,4'-(1-methylethylidene)bis[phenol] and methyloxirane (9CI) (CA INDEX NAME)

CM 1

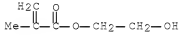
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1— Me

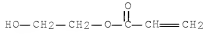
CM 2

CRN 868-77-9
CMF C6 H10 O3



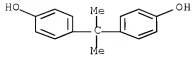
CM 3

CRN 818-61-1
CMF C5 H8 O3



CM 4

CRN 80-05-7
CMF C15 H16 O2



CM 5

CRN 79-41-4
CMF C4 H6 O2

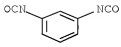
CM 6

CRN 75-56-9
CMF C3 H6 O

IT 73920-35-1
RL: TEM (Technical or engineered material use); USES (Uses)
(coatings, on tinplates, UV-curable)
RN 73920-35-1 HCAPLUS
CN 2-Propenoic acid, 2-methyl-, 2-hydroxyethyl ester, polymer with 1,3-diisocyanatomethylbenzene, 2-hydroxyethyl 2-propenoate, 2-hydroxypropyl 2-propenoate, 4,4'-(1-methylethylidene)bis[phenol], methyloxirane and 2-propenoic acid (9CI) (CA INDEX NAME)

CM 1

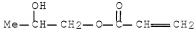
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1— Me

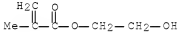
CM 2

CRN 999-61-1
CMF C6 H10 O3



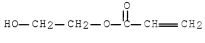
CM 3

CRN 868-77-9
CMF C6 H10 O3



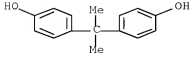
CM 4

CRN 818-61-1
CMF C5 H8 O3



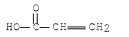
CM 5

CRN 80-05-7
CMF C15 H16 O2



CM 6

CRN 79-10-7
CMF C3 H4 O2



CM 7

CRN 75-56-9
CMF C3 H6 O

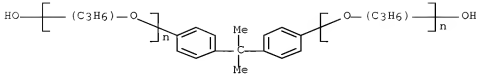
L110 ANSWER 37 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1980:130198 HCAPLUS Full-text
DN 92:130198
OREF 92:21233a,21236a
TI Photosensitive adhesive compositions
IN Sumita, Yuzo; Meiwa, Zenpei; Minakata, Masaaki
PA Kao Soap Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 12 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 54133527	A	19791017	JP 1978-41976	19780410 <--
JP 60024825	B	19850614		
PRAI JP 1978-41976	A	19780410 <--		

AB Adhesives are prepared from polyoxypropylated bisphenol A (I), hydroxyethyl (meth)acrylate, maleic anhydride (II), and polyisocyanates. Thus, 2 mol I and 1.01 mol II are heated at 220° to acid number <8, mixed with 0.05% hydroquinone and 2.02 mol 2-hydroxyethyl acrylate (III), dehydrated at 95° in vacuo, mixed with 2 mol TDI, and heated at 75-115° for 45 min and 125-8° for 5 h to give a polymer [73061-89-9] which is mixed (50 parts) with 50 parts III and 5 parts benzoin iso-Bu ether, used to bond glass, and irradiated with a high-pressure Hg lamp to give adhesion 45.2 kg/cm2.
IT 73046-81-8
RL: TEM (Technical or engineered material use); USES (Uses)
(adhesives, photocurable)
RN 73046-81-8 HCAPLUS
CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 1,3-diisocyanatomethylbenzene and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

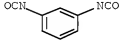
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



CM 2

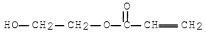
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1— Me

CM 3

CRN 818-61-1
CMF C5 H8 O3



L110 ANSWER 38 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1977:73651 HCAPLUS Full-text
DN 86:73651
OREF 86:11681a,11684a
TI Radically crosslinkable thixotropic polymer compositions
IN Fujimoto, Hiroshi; Suzuki, Hajime; Miyake, Hideo
PA Toyobo Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 12 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 51116851	A	19761014	JP 1975-42452	19750407 <--

PRAI JP 1975-42452 A 19750407 <--

AB The compns. comprised thixotropic bis(3-hydroxy-2,2-dimethylpropyl) terephthalate-Desmodur T 80-ethylene glycol monomethacrylate copolymer (I) [61509-32-8] or a similar urethane-modified acrylate resin and unsatd. polyesters or vinyl ester resins. Thus, a mixture of styrene 641, bis(3-hydroxy-2,2-dimethylpropyl) terephthalate 338, and hydroquinone 0.16 part was heated to 50°, mixed with 348 parts Desmodur T 80 at <80° to give an isocyanate-terminated prepolymer, treated with 286 parts ethylene glycol monomethacrylate at <80° to give I, diluted (100 parts) with 20 parts styrene, and mixed with a 50% solution of bisphenol A-propylene oxide adduct (1:2)-fumaric acid copolymer [39382-25-7] in styrene in ratio 4:6 to prepare a composition having good pot life.

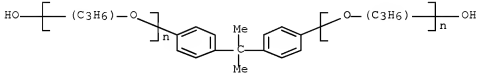
IT 61509-39-5 61509-40-8
RL: USES (Uses)
(thixotropic, containing unsatd. polyesters)

RN 61509-39-5 HCAPLUS

CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with 1,3-diisocyanatomethylbenzene, 4,4'-(1-methylethylidene)bis[cyclohexanol] and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

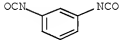
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



CM 2

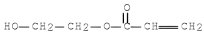
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1— Me

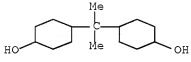
CM 3

CRN 818-61-1
CMF C5 H8 O3



CM 4

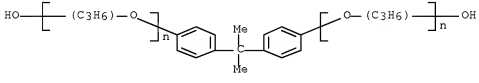
CRN 80-04-6
CMF C15 H28 O2



RN 61509-40-8 HCAPLUS
CN 2-Propenoic acid, 2-methyl-, 2-hydroxypropyl ester, polymer with 1,6-diisocyanatohexane, 1,3-diisocyanatomethylbenzene, 4,4'-(1-methylethylidene)bis[cyclohexanol] and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

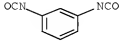
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



CM 2

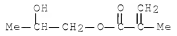
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1— Me

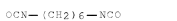
CM 3

CRN 923-26-2
CMF C7 H12 O3



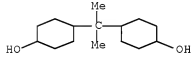
CM 4

CRN 822-06-0
CMF C8 H12 N2 O2



CM 5

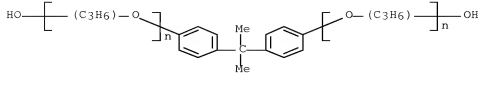
CRN 80-04-6
CMF C15 H28 O2



IT 61509-43-1
RL: USES (Uses)
(thixotropic, containing vinyl ester resins)
RN 61509-43-1 HCAPLUS
CN 2-Propenoic acid, 2-methyl-, 2-hydroxyethyl ester, polymer with 1,1'-methylenebis[4-isocyanatobenzene] and α,α'-[(1-methylethylidene)di-4,1-phenylene]bis[ω-hydroxypoly[oxy(methyl-1,2-ethanediyl)]] (9CI) (CA INDEX NAME)

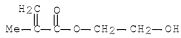
CM 1

CRN 37353-75-6
CMF (C3 H6 O)n (C3 H6 O)n C15 H16 O2
CCI IDS, PMS



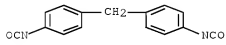
CM 2

CRN 868-77-9
CMF C6 H10 O3



CM 3

CRN 101-68-8
CMF C15 H10 N2 O2



L110 ANSWER 39 OF 39 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1973:419799 HCAPLUS Full-text
DN 79:19799
OREF 79:3187a,3190a
TI Heat-hardenable resin compositions
IN Takamori, Shigeru; Meiwa, Zenpei; Sakaguchi, Kahei
PA Kao Soap Co., Ltd.
SO Jpn. Kokai Tokkyo Koho, 2 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

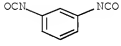
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 48025095	A	19730402	JP 1971-58151	19710802 <--
PRAI JP 1971-58151	A	19710802 <--		

AB OCN-terminated urethane prepolymers obtained by treating isocyanates in the ratio 1.5-2:1 mole with divalent phenol-polyoxyalkylene adducts in styrene (I), acrylonitrile, or Me methacrylate, were treated with 2-hydroxyethyl methacrylate(II[to give thermosetting resins used in fiber-reinforced plastic manufacturing Thus, a solution of 1:1 bisphenol A-propylene oxide adduct [9039-29-6] 354, triethylenediamine 0.96, and hydroquinone 0.38 g in 640 g I was added dropwise at 80.deg. during 1 hr to 348 g tolylene diisocyanate [26471-62-5], mixed at <80.deg. during dropwise addition in 30 min to 260 g II, and cured 2 hr at 50.deg. to give a resin. The resin (40% I, OH value 4.2, viscosity at 25.deg. 755 cP) was mixed with Me Et ketone peroxide, dimethylaniline, Co naphthenate, and glass chopped strand mats to give test sheets, whose bending strength decreased from 12 to 10.1 kg/mm2 after 6 months immersion in 30% aqueous chromic acid at 20.deg..
IT 29444-86-5
RL: USES (Uses)
(glass fiber-reinforced, heat-hardenable)

RN 39444-86-5 HCAPLUS
CN 2-Propenoic acid, 2-methyl-, 2-hydroxyethyl ester, polymer with 1,3-diisocyanatomethylbenzene, 4,4'-(1-methylethylidene)bis[phenol] and methyloxirane (9CI) (CA INDEX NAME)

CM 1

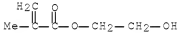
CRN 26471-62-5
CMF C9 H6 N2 O2
CCI IDS



D1—Me

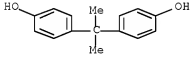
CM 2

CRN 868-77-9
CMF C6 H10 O3



CM 3

CRN 80-05-7
CMF C15 H16 O2



CM 4

CRN 75-56-9
CMF C3 H6 O

=>